RV1126_RV1109 Reference Design

RV1126_RV1109_IPC_REF_V1.2

RV1126_RV1109 Main difference		
	RV1126	RV1109
CPU	Quad A7	Dual A7
NPU	2.0Tops	1.2Tops
ISP	14M Pixel	5M Pixel

Reference Design Main Functions Introduction	
Power	RK809-2 +1DCDC or Discrete Power
RAM	EMMC/SLC NAND FLASH/SPI FLASH
ROM	DDR3L/DDR3/LPDDR3/LPDDR4
Interface	SDMMC/SDIO/MAC/LCD/CIF/MIPI_DSI/MIPI_CSI0/ MIPI_CSI1/LVDS0/LVDS1/I2S/PDM/USB/ADC

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	00.Cover Page				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	1 of 44

Table of Content

Index and Notes

Note

NOTE 1:
Component parameter description
1. DNP stands for component not mounted temporarily
2. If Value or option is DNP, which means the area is reserved without being mounted

NOTE 2:
Please use our recommended components to avoid too many changes.
For more informations about the second source,please refer to our AVL.

Generate Bill of Materials

Header:

Item\tPart\tDescription\tPCB Footprint\tReference\tQuantity\tOption

Combined property string:

{Item}\t{Value}\t{Description}\t{PCB Footprint}\t{Reference}\t{Quantity}\t{Option}

Graphic Description

Note

Option

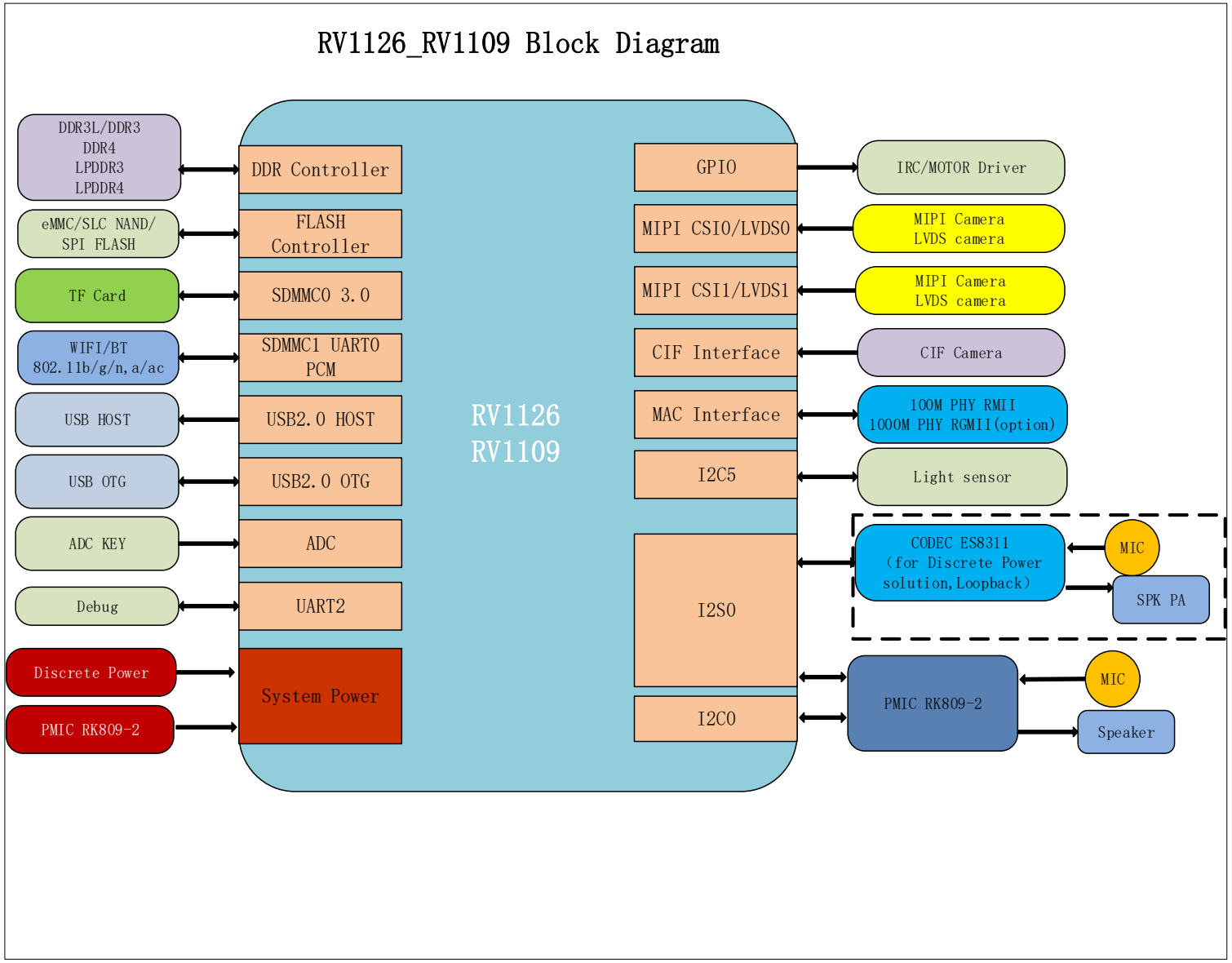
Description

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	01.Index and Notes				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	2 of 44

Revision History

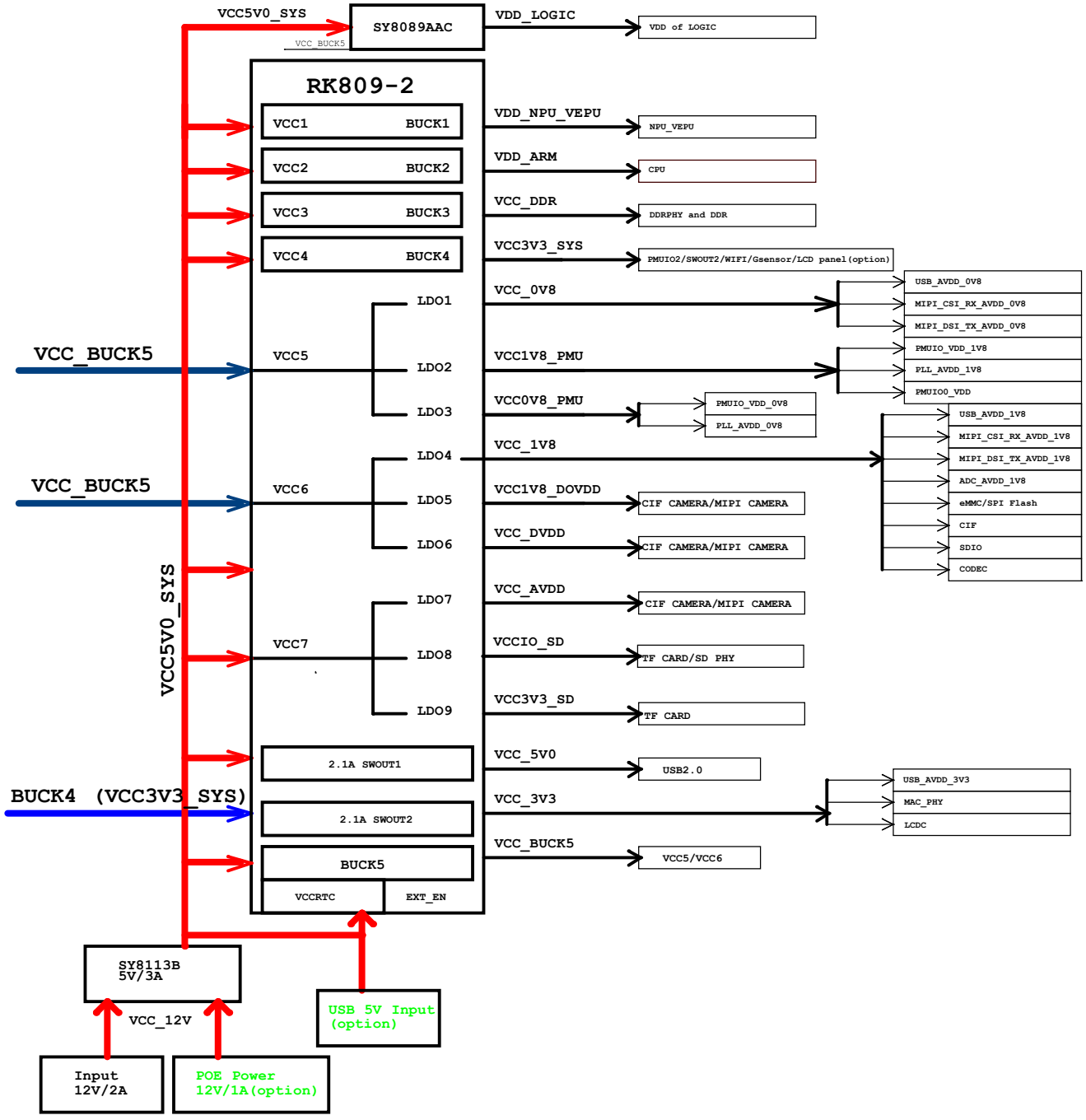
Version	Date	Author	Change Note	Approved
V1.0	2020.04.09	Liyh	IPC REF Design V1.0 for RV1126_RV1109	
V1.1	2020.06.26	Liyh	IPC REF Design V1.1 for RV1126_RV1109 Update: 1.Add usb circuit for improving compability 2.Replace DDR3 template 3.Update some notes	
V1.2	2020.11.02	Liyh	IPC REF Design V1.2 for RV1126_RV1109 Update: 1. Add discrete power solution. 2. Add the discrete CODEC IC solution. 3. Change the IRCUT, PAN/TILT Driver.	

RV1126_RV1109 Block Diagram



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	03.Block Diagram				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	4 of 44

PMIC Power Diagram



The reference power on sequence of RK809-2 and discrete BUCK

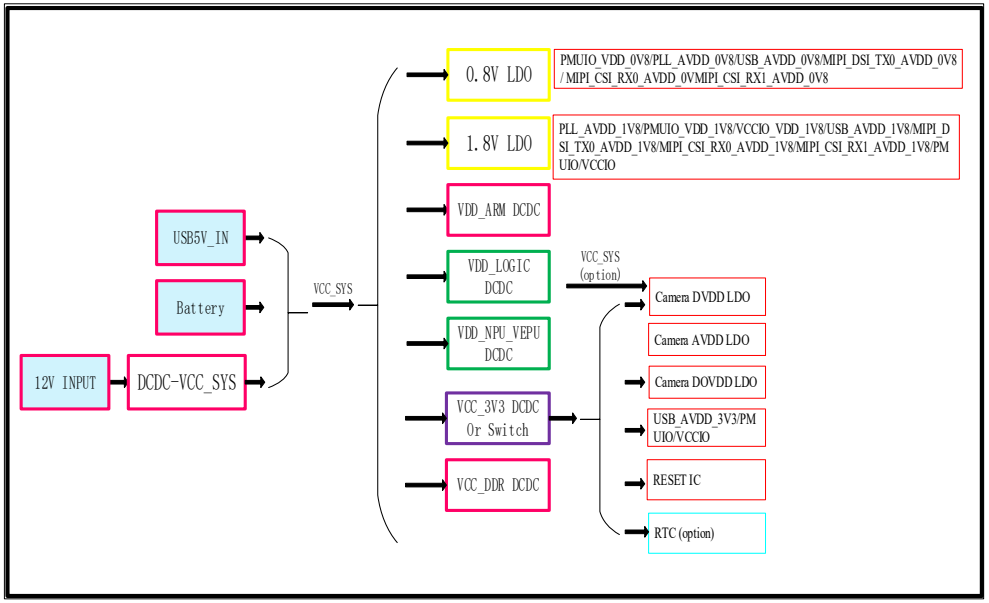
Power Name	PMIC Channel	Time (step=2ms)	Default voltage	Supply Limit	Default ON/OFF	Sleep ON/OFF	Peak Current
VCC_BUCK5	RK809-2 BUCK5	Slot: 1	2.2V	2.5A	ON	ON	
VCC0V8_PMU	RK809-2 LDO3	Slot: 2	0.8V	0.1A	ON	ON	
VCC_0V8	RK809-2 LDO1	Slot: 2	0.8V	0.4A	ON	OFF	
VDD_ARM	RK809-2 BUCK2	Slot: 2	0.8V	2.5A	ON	OFF	0.73A@1.8GHz
VDD_NPU	RK809-2 BUCK1	Slot: 2	0.8V	2.0A	ON	OFF	1.34A@934MHz
VDD_VEPU	RK809-2 BUCK1	Slot: 2	0.8V	2.0A	ON	OFF	0.77A@700MHz
VDD_LOGIC	Ext(SY8089AAC)	Slot 1+3ms	0.8V	2.5A	ON	ON	1.75A
VCC_DDR	RK809-2 BUCK3	Slot: 3	1.5V	1.5A	ON	ON	
VCC1V8_PMU	RK809-2 LDO2	Slot: 3	1.8V	0.4A	ON	ON	
VCC_1V8	RK809-2 LDO4	Slot: 3	1.8V	0.4A	ON	OFF	
VCC3V3_SYS	RK809-2 BUCK4	Slot: 4	3.3V	1.5A	ON	ON	
VCC_3V3	RK809-2 SWOUT2	Slot: 4	3.3V	1.5A	ON	OFF	
VCCIO_SD	RK809-2 LDO8	Slot: 4	3.3V	0.4A	ON	OFF	
VCC3V3_SD	RK809-2 LDO9	Slot: 4	3.3V	0.4A	ON	OFF	
VCC1V8_DOVDD	RK809-2 LDO5		1.8V	0.4A	OFF	OFF	
VCC_DVDD	RK809-2 LDO6		1.2V	0.4A	OFF	OFF	
VCC_AVDD	RK809-2 LDO7		2.8V	0.4A	OFF	OFF	
VCC5V0_HOST	RK809-2 SWOUT1		5V	2.1A	ON	OFF	
RESET	RK809-2 sent out Reset signal for soc(SLOT:5(10ms))						

NOTE:VCC_DVDD and VCC_AVDD according to camera sensor voltage

Example: PMIC RK809-2 Solution Table of Content

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	04.PMIC Power Diagram				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	5 of 44

Power Diagram



The reference power on sequence of discrete power

Power Name	Power Channel	the requirement of power on sequence	Default voltage	Supply Limit	Peak Current
VCC_0V8	LDO	1	0.8V	0.5A	
VDD_LOGIC	BUCK	2	0.8V	2.0A	1.75A
VDD_ARM	BUCK	2	0.8V	1.0A	0.73A
VDD_NPU_VEPU	BUCK	2	0.8V	3.0A	2.11A
VCC_1V8	LDO	3	1.8V	0.5A	
VCC_DDR	BUCK	4	1.1V/1.2V/1.35V/1.5V	2.0A	
VCC_3V3	BUCK or Switch	5	3.3V	2.0A	
VCC1V8_DOVDD	LDO		1.8V	0.5A	
VCC1V2_DVDD	LDO		1.2V	0.5A	
VCC2V8_AVDD	LDO		2.8V	0.5A	
RESET					

NOTE:VCC_DVDD and VCC_AVDD according to camera sensor voltage

Example: Discrete Solution Table of Content

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	05.Discrete Power Diagram				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	6 of 44

I2C MAP

Port	Pin Name	Domain	Bus Name	Pull-up voltage	Slave Device	Slave Addr (MS 7Bits)	Slave Bus Capability	Note
I2C0	I2C0_SCL/GPIO0_B4_u I2C0_SDA/GPIO0_B5_u	PMUIO1	I2C0_SCL_PMIC I2C0_SDA_PMIC	VCC3V3_SYS	RK809-2	0x20		PMIC
I2C1	I2C1_SCL/GPIO1_D3_u I2C1_SDA/GPIO1_D2_u	VCCIO4	I2C1_SCL I2C1_SDA	VCC1V8_DOVDD				CIF camera
								MIPI camera
I2C2	I2C2_SCL/GPIO0_C2_d I2C2_SDA/GPIO0_C3_d	PMUIO1	I2C2_SCL I2C2_SDA	VCC3V3_SYS	RTC			
I2C4	I2C4_SCL_M1/GPIO4_A0_d I2C4_SDA_M1/GPIO4_A1_d	VCCIO7	I2C4_SCL I2C4_SDA	VCC_3V3	ES8311			
I2C5	I2C5_SCL_M0/GPIO2_A5_d I2C5_SDA_M0/GPIO2_B3_d	VCCIO5	I2C5_SCL I2C5_SDA	VCC_3V3	MS32006 CM32181A3OP			

IO Power Domain Map

IO Domain	IO Group	Support of IO Voltage		Default Actual assigned IO Domain Voltage			Notes
		1.8V	3.3V	Net Name of Power Supply	Power Source	Voltage	
PMUIO0	***GPIO0A***	✓	✓	*VCC1V8_PMU*	*RK809-2_LDO2*	*1.8V*	
PMUIO1	***GPIO0BC***	✓	✓	*VCC3V3_SYS*	*RK809-2_BUCK4*	*3.3V*	
VCCIO1	***GPIO0CD/GPIO1A***	✓	✓	*VCCIO_FLASH*	*RK809-2_LDO4*	*1.8V*	*GPIO0_B3/FLASH_VOL_SEL pin defined as a set pin for VCCIO1 voltage.*
VCCIO2	***GPIO1AB***	✓	✓	*VCCIO_SD*	*RK809-2_LDO8*	*3.3V*	
VCCIO3	***GPIO1BCD***	✓	✓	*VCCIO3_VDD*	*RK809-2_LDO4*	*1.8V*	
VCCIO4	***GPIO1D/GPIO2A***	✓	✓	*VCCIO4_VDD*	*RK809-2_LDO4*	*1.8V*	
VCCIO5	***GPIO2ABCD/GPIO3A***	✓	✓	*VCCIO5_VDD*	*RK809-2_SWOUT2*	*3.3V*	
VCCIO6	***GPIO3ABC***	✓	✓	*VCCIO6_VDD*	*RK809-2_LDO4*	*1.8V*	
VCCIO7	***GPIO3D/GPIO4A***	✓	✓	*VCCIO7_VDD*	*RK809-2_LDO4*	*1.8V*	

Power

U1000N
RV1126/RV1109
BGA409 14R00X14R00X0R90

NPU/LOGIC/VEPU/ARM Power

NPU_VDD_1	H11	VDD_NPU_VEPU
NPU_VDD_2	H12	
NPU_VDD_3	J10	
NPU_VDD_4	J11	
NPU_VDD_5	K10	
NPU_VDD_6	K11	
LOGIC_VDD_1	H9	VDD_LOGIC
LOGIC_VDD_2	J9	
LOGIC_VDD_3	L10	
LOGIC_VDD_4	M11	
LOGIC_VDD_5	H13	
LOGIC_VDD_6	J13	
VEPU_VDD_1	L9	VDD_NPU_VEPU
VEPU_VDD_2	M9	
VEPU_VDD_3	N8	
VEPU_VDD_4	N9	
ARM_VDD_1	N12	VDD_ARM
ARM_VDD_2	P12	
ARM_VDD_3	P13	

Supply for VCCIO1~7 Power

VCCIO_VDD_1V8 — H14 — R1000 3.3R R0402 1% — VCC_1V8

C1000 1nF X5R 25V C0201

NOTE:
If any power domain of vccio 1 ~ vccio 7 is used,
then VCCIO_ VDD_ 1V8 must be connected to 1.8V power supply

VDD_NPU_VEPU

C1006 10uF X5R 4V C0402
C1005 1uF X5R 6.3V C0402
C1004 1uF X5R 6.3V C0402
C1003 100nF X5R 6.3V C0201
C1002 100nF X5R 6.3V C0201
C1001 100nF X5R 6.3V C0201

For NPU Power

VDD_NPU_VEPU

C1019 10uF X5R 4V C0402
C1018 1uF X5R 6.3V C0402
C1017 100nF X5R 6.3V C0201
C1016 100nF X5R 6.3V C0201

For VEPU Power

VDD_ARM

C1015 10uF X5R 4V C0402
C1014 1uF X5R 6.3V C0402
C1013 100nF X5R 6.3V C0201
C1012 100nF X5R 6.3V C0201

VDD_LOGIC

C1011 10uF X5R 4V C0402
C1009 1uF X5R 6.3V C0402
C1010 1uF X5R 6.3V C0402
C1007 100nF X5R 6.3V C0201
C1008 100nF X5R 6.3V C0201

GND

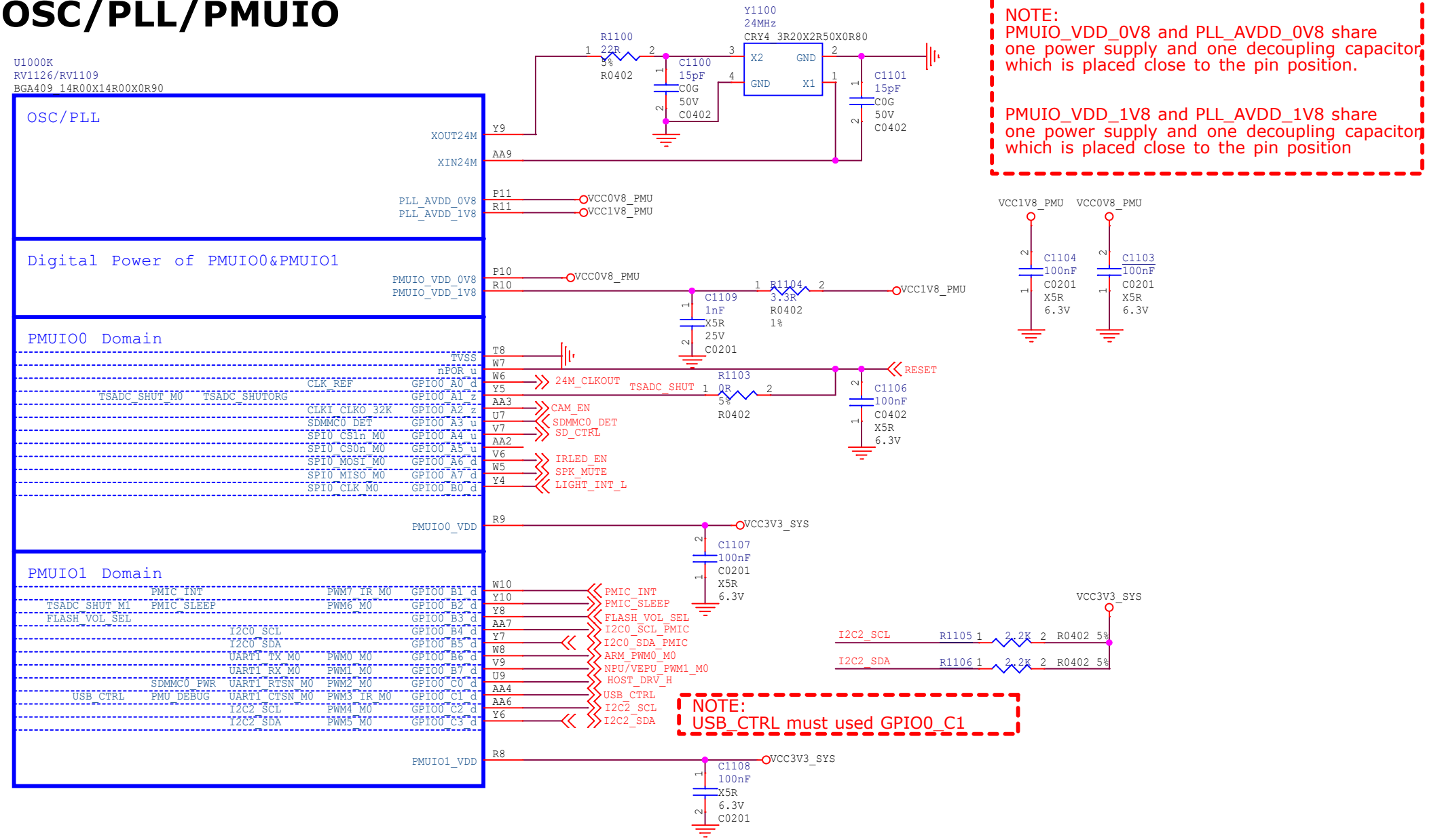
U1000O
RV1126/RV1109
BGA409 14R00X14R00X0R90

VSS/AVSS

A1	VSS_1	VSS_53	K9		
A21	AVSS_2	VSS_54	K12		
B12	VSS_3	VSS_55	K13		
C3	VSS_4	VSS_56	K14		
C5	VSS_5	VSS_57	L2		
C7	VSS_6	VSS_58	L5		
C10	VSS_7	VSS_59	L6		
C12	VSS_8	VSS_60	L11		
D9	VSS_9	VSS_61	L12		
D12	VSS_10	VSS_62	L13		
D18	AVSS_11	VSS_63	L14		
E4	VSS_12	VSS_64	L16		
E6	VSS_13	VSS_65	M3		
E8	VSS_14	VSS_66	M5		
E9	VSS_15	VSS_67	M7		
E10	VSS_16	VSS_68	M8		
E11	VSS_17	VSS_69	M10		
E12	VSS_18	VSS_70	M12		
F3	VSS_19	VSS_71	M13		
F5	VSS_20	VSS_72	M14		
F7	VSS_21	VSS_73	M16		
F8	VSS_22	VSS_74	N5		
F9	VSS_23	VSS_75	N6		
F10	VSS_24	VSS_76	N7		
F11	VSS_25	VSS_77	N10		
F12	VSS_26	VSS_78	N11		
F13	VSS_27	VSS_79	N13		
F14	AVSS_28	VSS_80	N14		
F15	AVSS_29	VSS_81	N16		
G2	VSS_30	VSS_82	P5		
G5	VSS_31	VSS_83	P7		
G6	VSS_32	VSS_84	P8		
G10	VSS_33	VSS_85	P9		
G11	VSS_34	VSS_86	P14		
G12	VSS_35	VSS_87	P16		
G13	VSS_36	VSS_88	R1		
G16	AVSS_37	VSS_89	R5		
G17	AVSS_38	VSS_90	R12		
H4	VSS_39	VSS_91	R13		
H5	VSS_40	VSS_92	R14		
H6	VSS_41	VSS_93	T6		
H7	VSS_42	VSS_94	T9		
H10	VSS_43	VSS_95	T10		
H15	VSS_44	VSS_96	T14		
J5	VSS_45	VSS_97	T17		
J6	VSS_46	VSS_98	V17		
J12	VSS_47	VSS_99	W9		
J14	VSS_48	VSS_100	W14		
J16	VSS_49	VSS_101	AA1		
K5	VSS_50	VSS_102	AA10		
K6	VSS_51	VSS_103	AA21		
K8	VSS_52				

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	10.RV1126/1109_Power/GND				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	9 of 44

OSC/PLL/PMUIO



NOTE:
PMUIO_VDD_0V8 and PLL_AVDD_0V8 share one power supply and one decoupling capacitor which is placed close to the pin position.

PMUIO_VDD_1V8 and PLL_AVDD_1V8 share one power supply and one decoupling capacitor which is placed close to the pin position

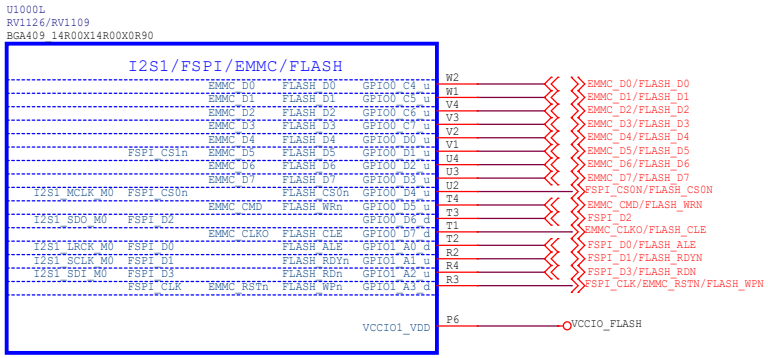
NOTE:
USB_CTRL must used GPIO0_C1

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	11.RV1126/1109_OSC/PLL/PMUIO				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	10 of 44

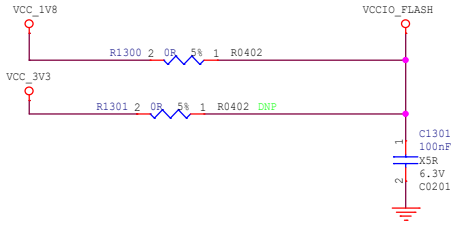
DDR Controller

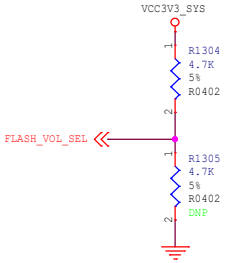
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd		
Project:	RV1126_RV1109 IPC REF		
File:	12.RV1126/1109_DRAM Controller		
Date:	Friday, December 04, 2020	Rev:	V1.2
Designed by: Yanhong.Li	Reviewed by: <Checker>	Sheet:	11 of 44

EMMC/FLASH



NOTE:
All the power filter capacitors should be placed close to the power pins of SOC.

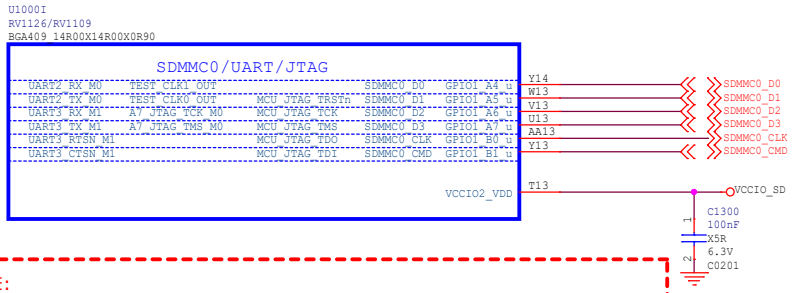




NOTE:
FLASH(VCCIO1) power domain IO supply configuration pin:

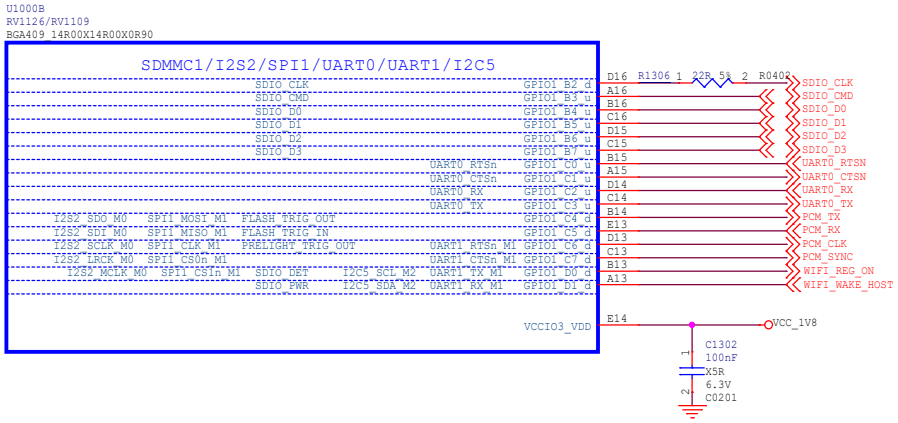
Condition	VCCIO1 (VCCIO_FLASH)
FLASH_VOL_SEL=0	3.3V
FLASH_VOL_SEL=1	1.8V Default

SDMMC0/JTAG



NOTE:
All the power filter capacitors should be placed close to the power pins of SOC.
If SD card is not used,please reserve MCU JTAG interface

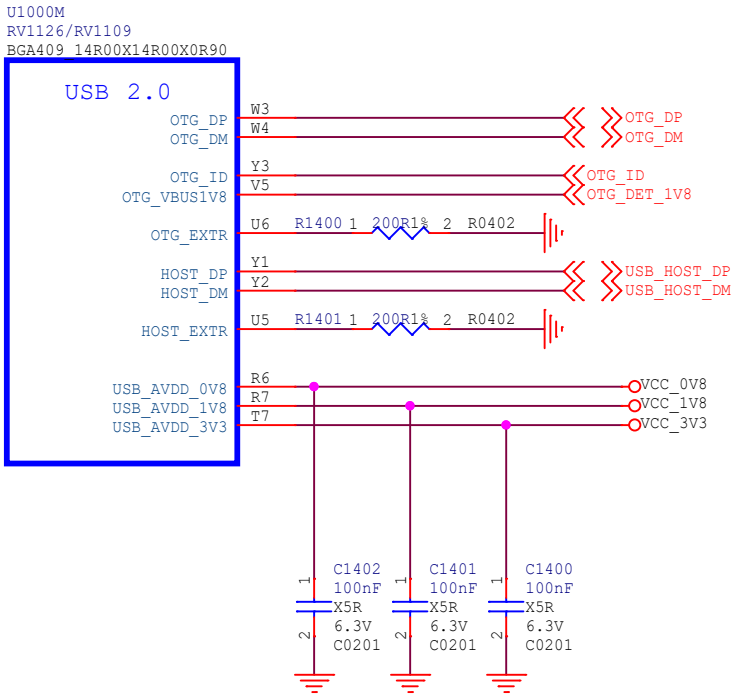
SDMMC1/UART/I2S2



NOTE:
All the power filter capacitors should be placed close to the power pins of SOC.

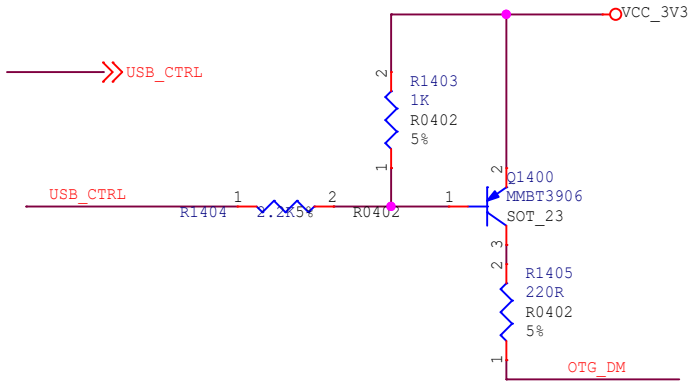
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	13.RV1126/1109_Flash/SD				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	12 of 44

USB Controller



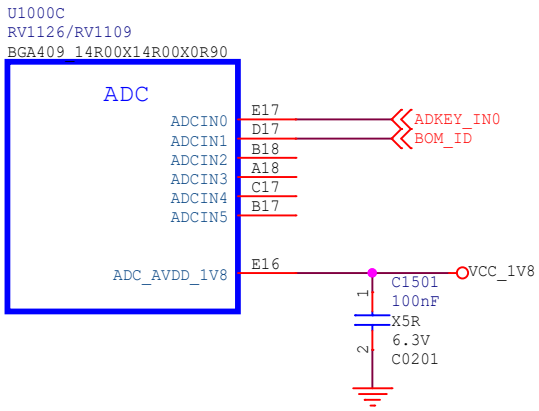
USB2.0 design rules:
1. Max intra-pair skew <4ps
2. Max trace length<6inchs
3. Max allowed via <6
4. Trace impedance 90ohm+/-10%
5. The distance between other signals follows the 3W rule.

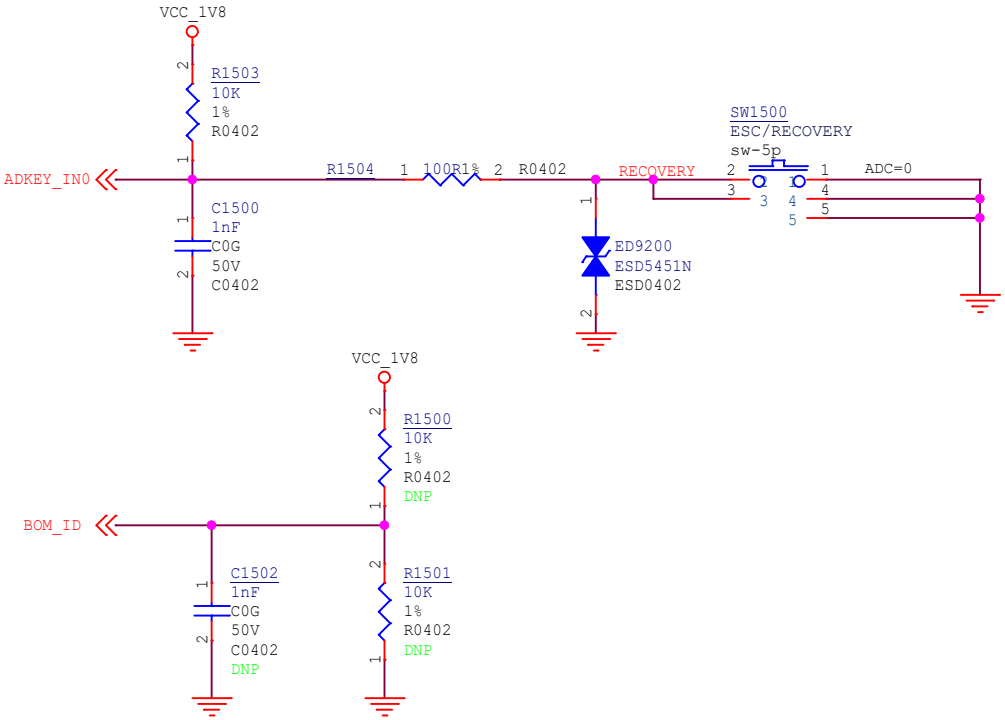
This circuit is used to improve usb compatibility.
Note:
These components are close to R2502 to avoid long branches.



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	14.RV1126/1109_USB Controller				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	13 of 44

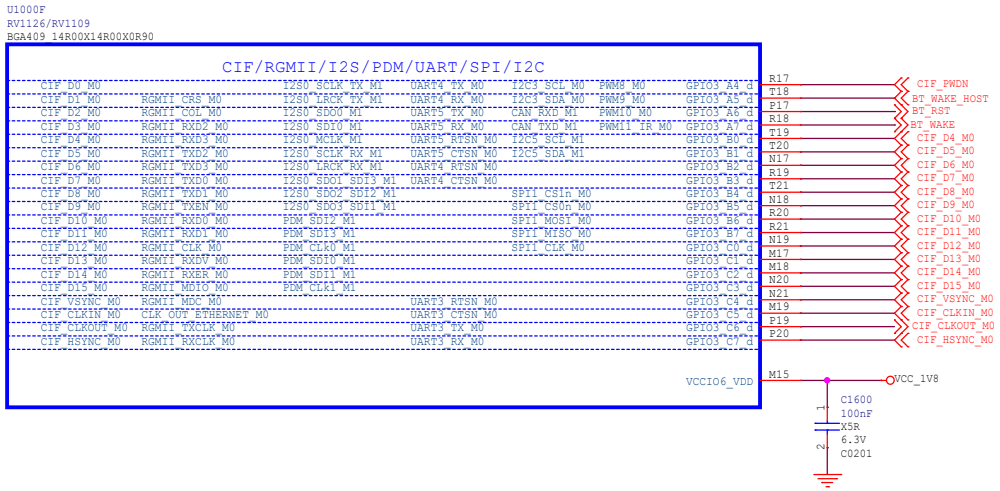
SARADC





Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	15.RV1126/1109_SARADC				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	14 of 44

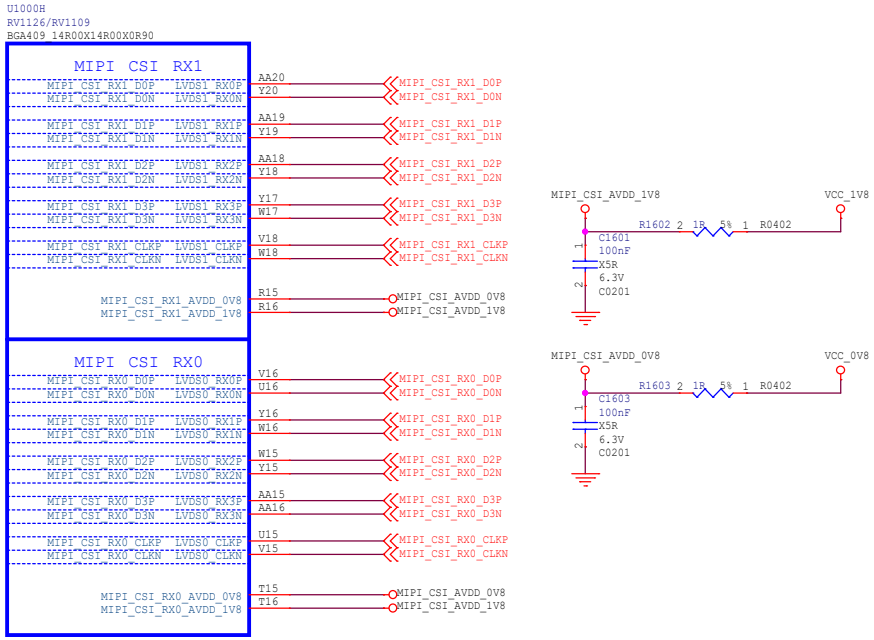
CIF Interface



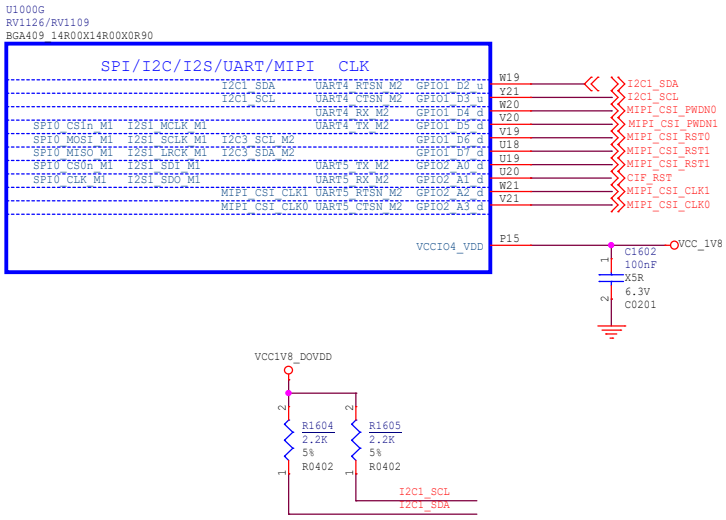
BT1120 RX	DATA:CIF_DATA[15:0] Y[0:7]:CIF_DATA[8:15] Cb[0:7]:CIF_DATA[0:7] CLOCK:CIF_CLKIN
12bit CIF camera	CameraCIF[11:0]:CIF_DATA[15:4] XCLK:CIF_CLKOUT PCLK:CIF_CLKIN HSYNC:CIF_HSYNC VSYNC:CIF_VSYNC
10bit CIF camera	CameraCIF[9:0]:CIF_DATA[15:6] XCLK:CIF_CLKOUT PCLK:CIF_CLKIN HSYNC:CIF_HSYNC VSYNC:CIF_VSYNC
8bit CIF camera	CameraCIF[7:0]:CIF_DATA[15:8] XCLK:CIF_CLKOUT PCLK:CIF_CLKIN HSYNC:CIF_HSYNC VSYNC:CIF_VSYNC

MIPI-CSI Interface

MIPI_CSI_RX0 and MIPI_CSI_RX1 power pins are adjacent, so they share a decoupling capacitor
All the power filter capacitors should be placed close to the power pins of SOC.

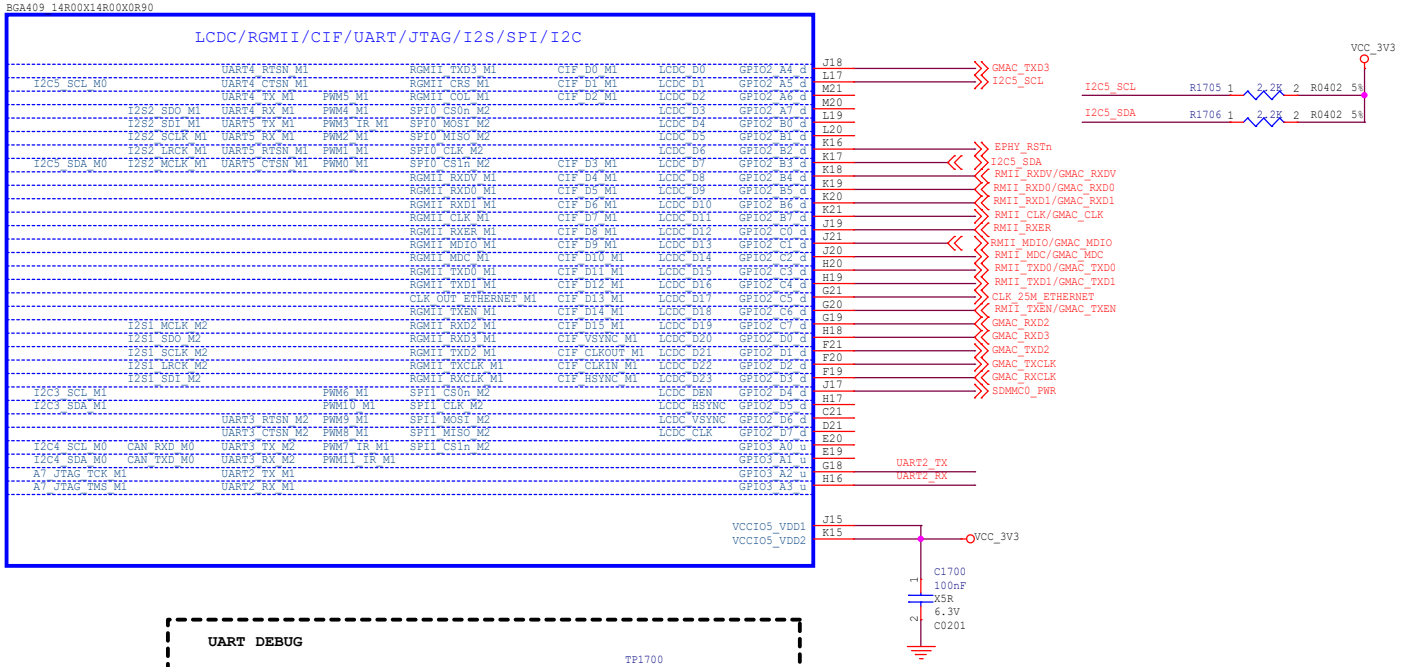


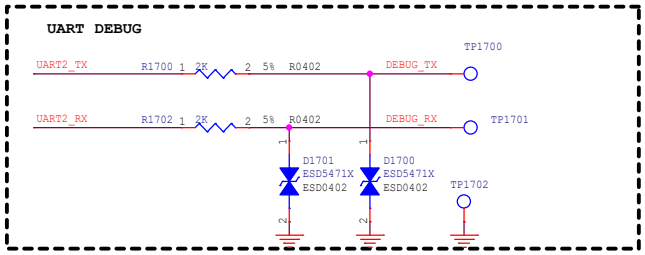
I2C/SPI/MIPI-CLK



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	16.RV1126/1109_VideoInput				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	15 of 44

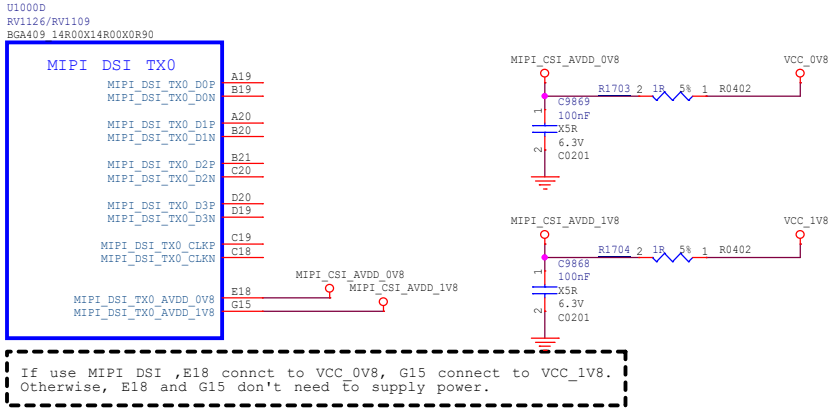
LCDC/RGMII/PWM





BT1120 TX	DATA:LCDC_DATA[15:0] Y[0:7]:LCDC_DATA[8:15] Cb[0:7]:LCDC_DATA[0:7] CLOCK:LCDC_CLK
6bit Serial RGB	DATA:LCDC_DATA[5:0] CLOCK:LCDC_CLK HSYNC:LCDC_HSYNC VSYNC:LCDC_VSYNC DE:LCDC_DEN
8bit Serial RGB	DATA:LCDC_DATA[7:0] CLOCK:LCDC_CLK HSYNC:LCDC_HSYNC VSYNC:LCDC_VSYNC DE:LCDC_DEN
16bit Parallel RGB(RGB565)	R[4:0]:LCDC_DATA[15:11] G[5:0]:LCDC_DATA[10:5] B[4:0]:LCDC_DATA[4:0] CLOCK:LCDC_CLK HSYNC:LCDC_HSYNC VSYNC:LCDC_VSYNC DE:LCDC_DEN
18bit Parallel RGB(RGB666)	R[5:0]:LCDC_DATA[17:12] G[5:0]:LCDC_DATA[11:6] B[5:0]:LCDC_DATA[5:0] CLOCK:LCDC_CLK HSYNC:LCDC_HSYNC VSYNC:LCDC_VSYNC DE:LCDC_DEN
24bit Parallel RGB(RGB888)	R[7:0]:LCDC_DATA[23:16] G[7:0]:LCDC_DATA[15:8] B[7:0]:LCDC_DATA[7:0] CLOCK:LCDC_CLK HSYNC:LCDC_HSYNC VSYNC:LCDC_VSYNC DE:LCDC_DEN

MIPI-DSI Interface



If use MIPI DSI ,E18 connct to VCC_0V8, G15 connect to VCC_1V8.
Otherwise, E18 and G15 don't need to supply power.

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	17.RV1126/1109_VideoOutput Interface				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	16 of 44

Audio Interface

U1000J
RV1126/RV1109
BGA409_14R00X14R00X0R90

I2S/PDM/ACODEC/I2C

I2S0_SCLK_TX_M0		ACODEC_DAC_CLK			GPIO3_D0_d	W12
I2S0_SCLK_RX_M0	PDM_CLK1_M0	ACODEC_ADC_CLK			GPIO3_D1_d	V12
I2S0_MCLK_M0					GPIO3_D2_d	U12
I2S0_LRCK_TX_M0		ACODEC_DAC_SYNC	AUDPWM_L_M1	AUDDSM_LN	GPIO3_D3_d	W11
I2S0_LRCK_RX_M0	PDM_CLK0_M0	ACODEC_ADC_SYNC			GPIO3_D4_d	Y12
I2S0_SDO0_M0		ACODEC_DAC_DATAR	AUDPWM_R_M1	AUDDSM_LP	GPIO3_D5_d	Y11
I2S0_SDI0_M0	PDM_SDI0_M0	ACODEC_DAC_DATAL			GPIO3_D6_d	AA12
I2S0_SDO1_SDI3_M0	PDM_SDI3_M0	ACODEC_ADC_DATA			GPIO3_D7_d	T11
I2S0_SDO2_SDI2_M0	PDM_SDI2_M0	I2C4_SCL_M1	AUDPWM_L_M0	AUDDSM_RN	GPIO4_A0_d	U11
I2S0_SDO3_SDI1_M0	PDM_SDI1_M0	I2C4_SDA_M1	AUDPWM_R_M0	AUDDSM_RP	GPIO4_A1_d	V11
					VCCIO7_VDD	T12

I2S0_SCLK_TX_M0
PDM_CLK1
I2S0_MCLK_M0
I2S0_LRCK_TX_M0
PDM_CLK
I2S0_SDO0_M0
I2S0_SDI0_M0
PDM_SDI3
I2C4_SCL_M1
I2C4_SDA_M1

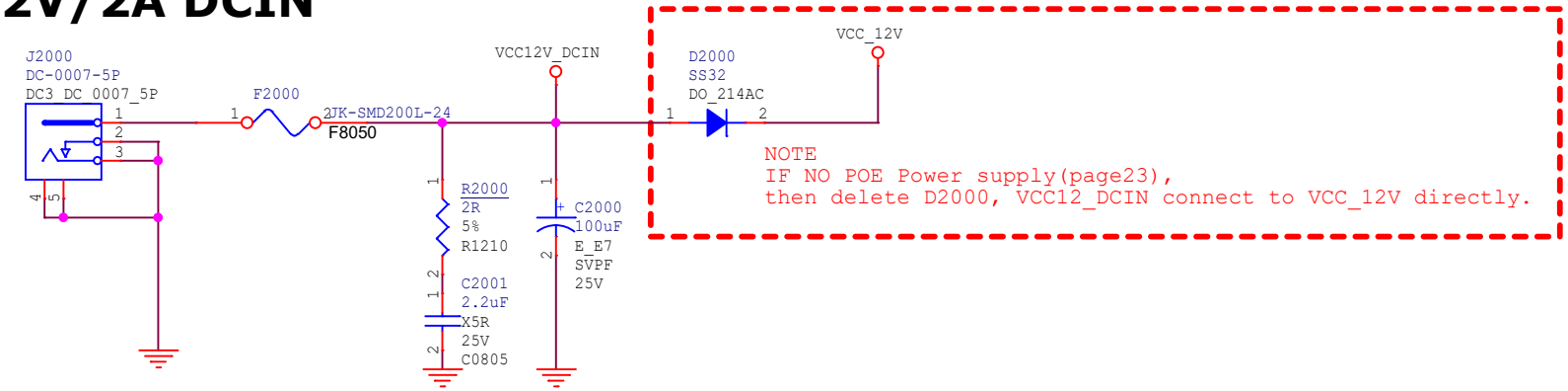
VCC_1V8
R1800 2 0R 5% 1 R0402
VCC_3V3
R1801 2 0R 5% 1 R0402 DNP

C1800
100nF
X5R
6.3V
C0201

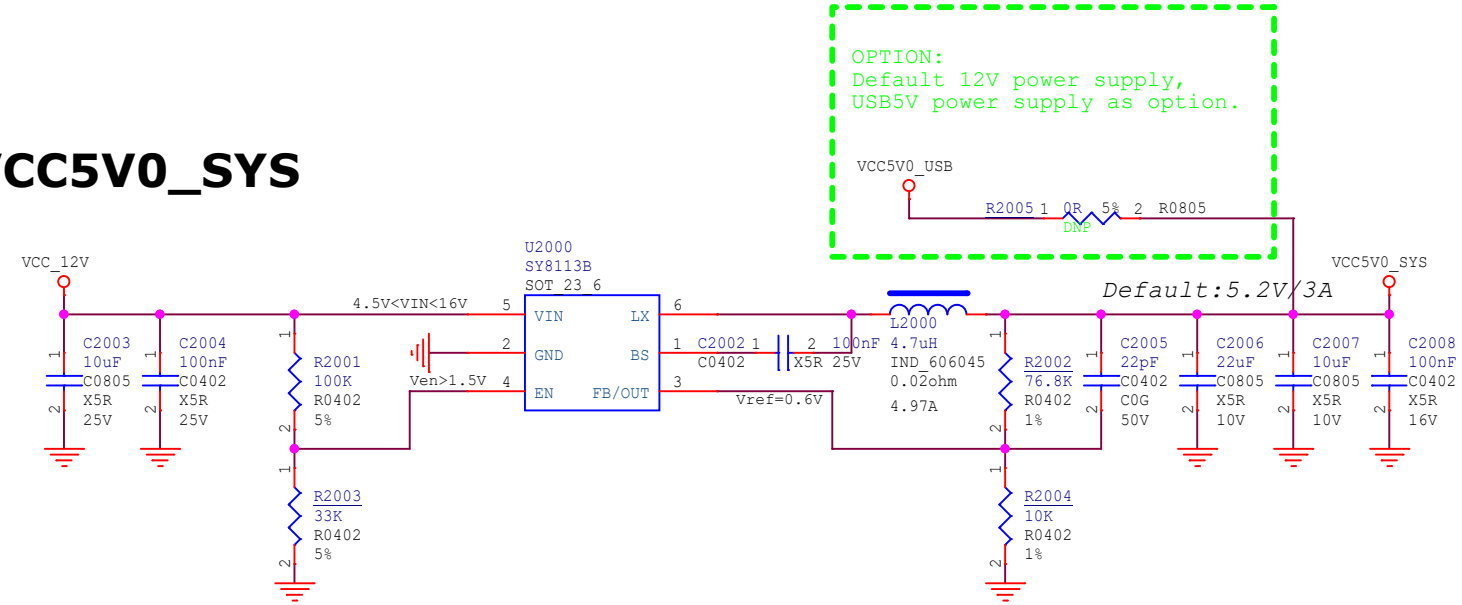
NOTE:
If the audio of RK809-2 is used, then R1800=0R, R1801=DNP
If the audio of ES8311 is used,then R1800=DNP,R1801=0R.

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	18.RV1126/1109_Audio				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	17 of 44

12V/2A DCIN



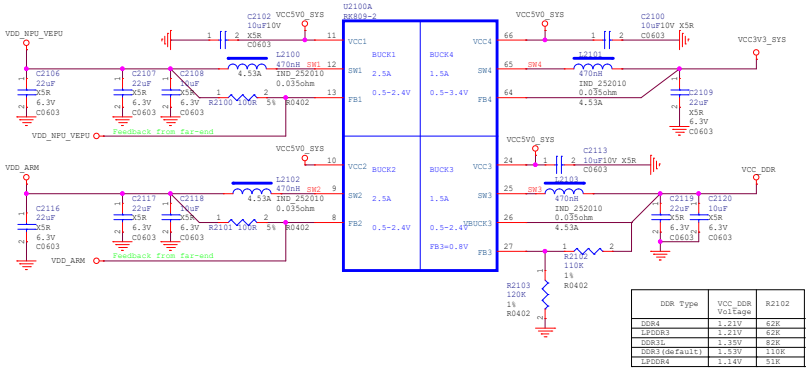
VCC5V0_SYS



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	20.Power_DC IN				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	18 of 44

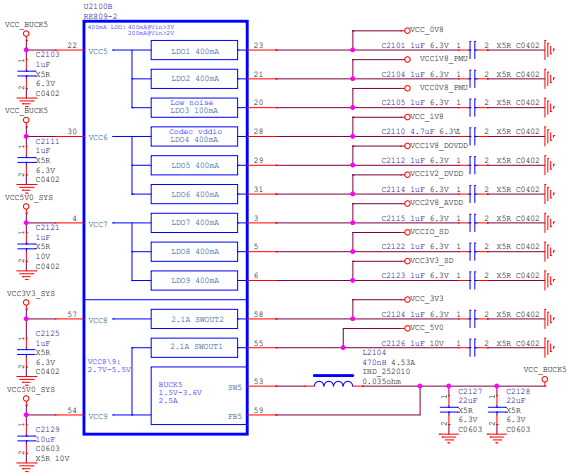
PMIC rk809-2 is recommended for the following solutions:
1) Rk1109 / rv1126 needs to be in standby mode;
2) There are more peripherals and solutions that need more power, such as those that require sd3.0 and screen functions.

PMIC RK809-2 DCDC

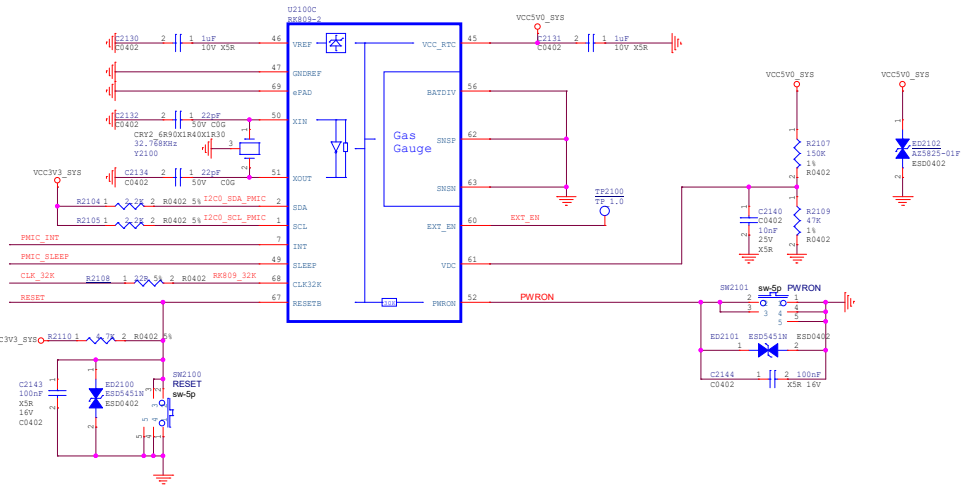


DDR Type	VCC_DDR Voltage	R2102
DDR4	1.21V	62K
LPDDR3	1.21V	62K
DDR3L	1.35V	82K
DDR3(default)	1.53V	110K
LPDDR4	1.14V	51K

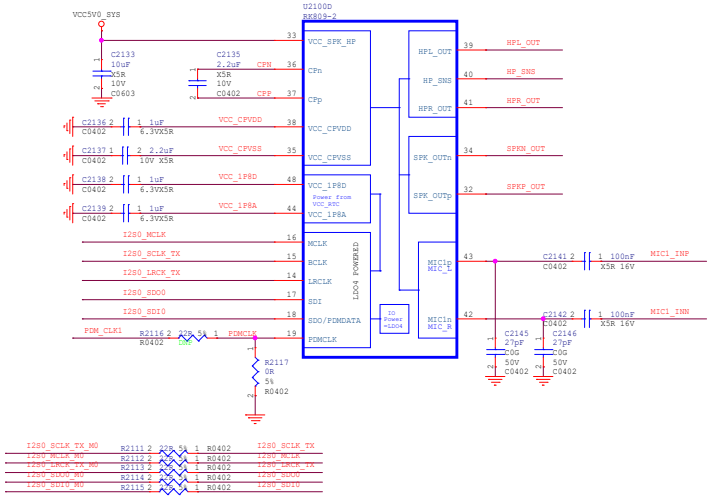
PMIC RK809-2 LDO



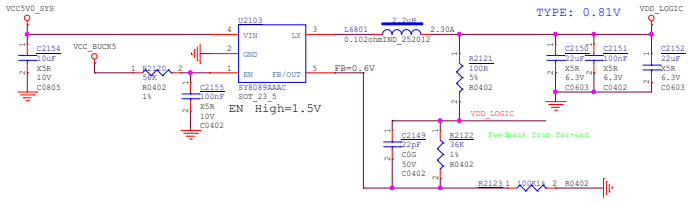
PMIC RK809-2 Managerment

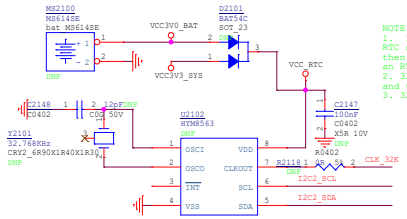


PMIC RK809-2 CODEC



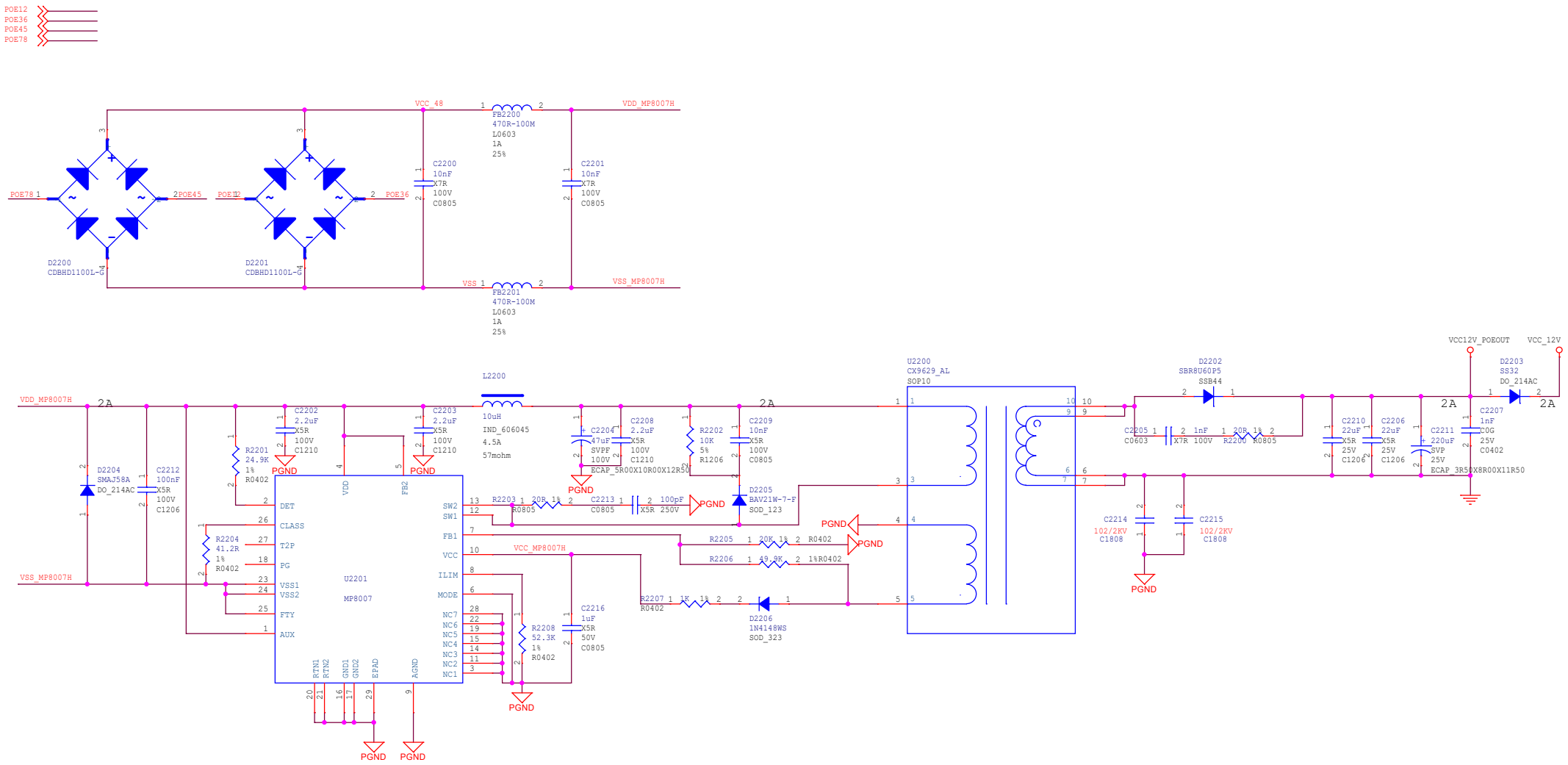
VDD_LOGIC





NOTE:
1. IPC: after the system is powered off, RTC still need to work, then it is necessary to add an RTC IC ,and use battery to power the RTC.
2. 32K crystal is connected to RTC, and the 32K crystal of rk809-2 can be DNP.
3. 32kclk signal can only be output from RTC.

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd
Project:	RV1126_RV1109 IPC REF
File:	21.Power_PMIC
Date:	Friday, December 04, 2020
Rev:	V1.2
Designed by:	Yanhong.Li
Reviewed by:	<Checker>
Sheet:	19 of 44



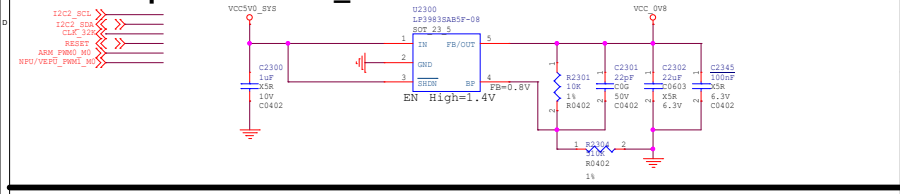
Class	Max Input Power to PD(W)	Classification Current(mA)	R2204(Rclass)
0	12.95	2	578R
1	3.84	10.55	110R
2	6.49	18.7	62R
3	12.95	28.15	41.2R
4	25.5	40.4	28.7R

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	23.POE Power(option)				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	20 of 44

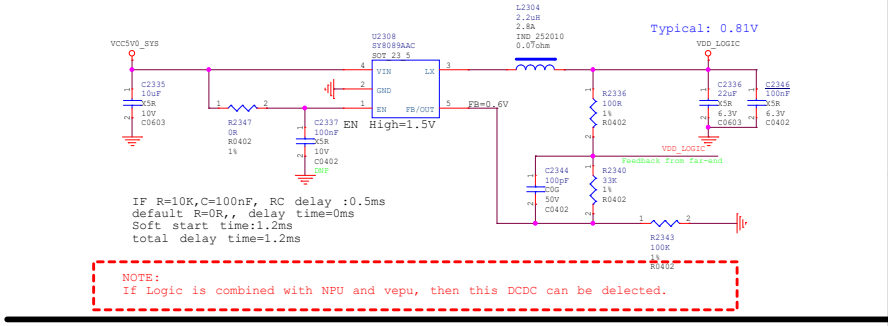
Discrete Power

Discrete power supply is recommended for the following solutions:
1) Less peripheral equipment and less power supply
2) Small PCB space
3) The following discrete power supply solutions can reduce some devices according to the actual products,
Please read the notes on the power supply below.

Power Sequence: 1 VCC_0V8

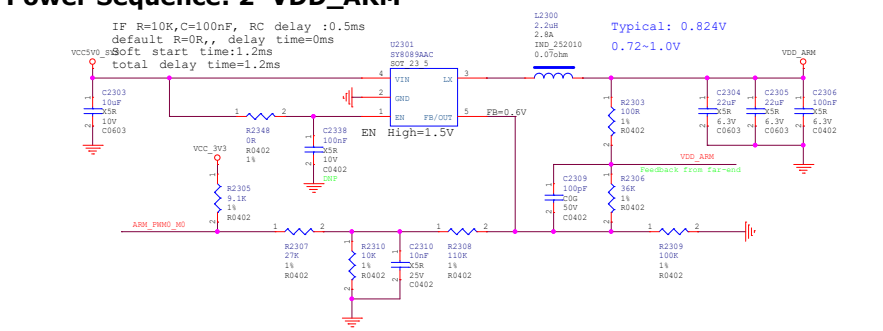


Power Sequence: 2 VDD_LOGIC

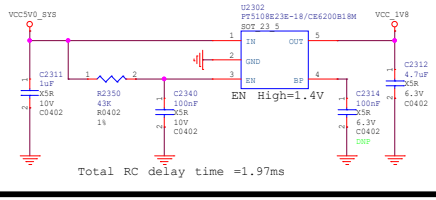


NOTE:
If Logic is combined with NPU and vepu, then this DCDC can be delected.

Power Sequence: 2 VDD_ARM

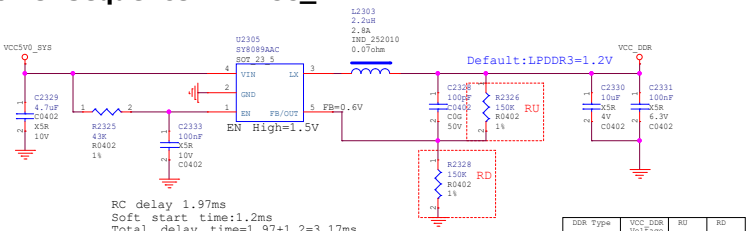


Power Sequence: 3 VCC_1V8



Total RC delay time =1.97ms

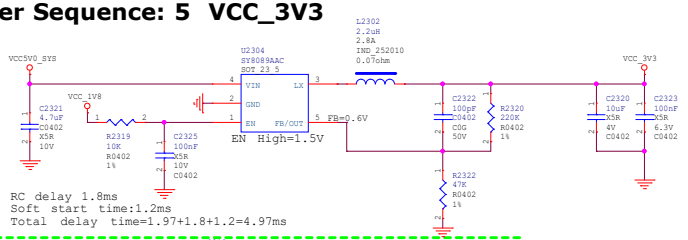
Power Sequence: 4 VCC_DDR



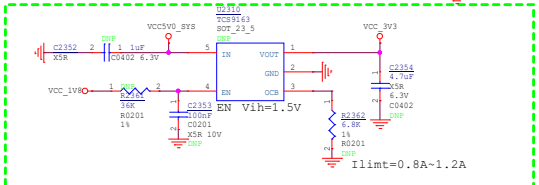
RC delay 1.97ms
Soft start time:1.2ms
Total delay time=1.97+1.2=3.17ms

DDR Type	VCC_DDR Voltage	RU	RD
DDR3L	1.35V	150K	120K
DDR3	1.5V	150K	100K
DDR4	1.2V	150K	150K
LPDDR3	1.2V	150K	150K
LPDDR4	1.1V	150K	180K

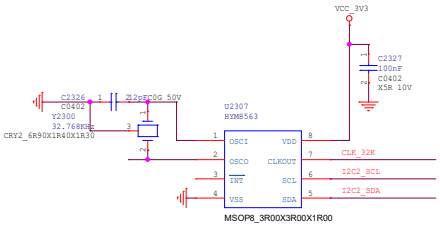
Power Sequence: 5 VCC_3V3

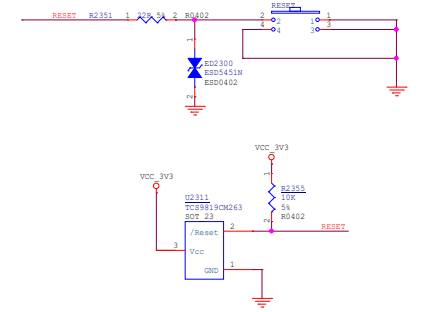


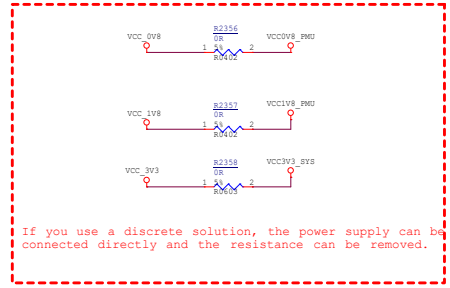
RC delay 1.8ms
Soft start time:1.2ms
Total delay time=1.97+1.8+1.2=4.97ms



NOTE:
Only when VCC5V0_SYS is 3.3V, the tcs9163 switch can be used.
then U2304 can be delected.



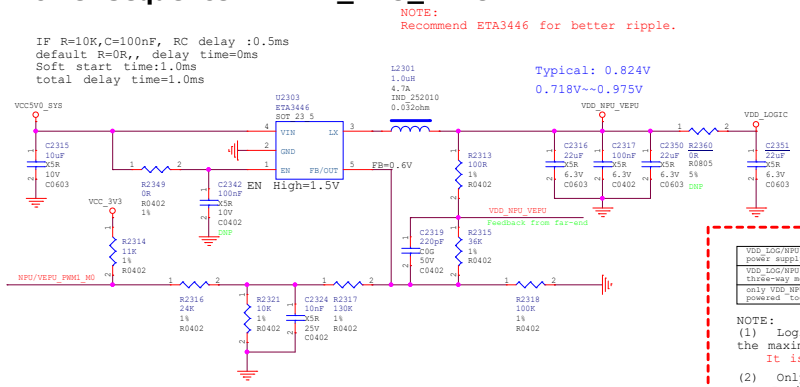




If you use a discrete solution, the power supply can be connected directly and the resistance can be removed.

Power Sequence: 2 VDD_NPU_VEPU

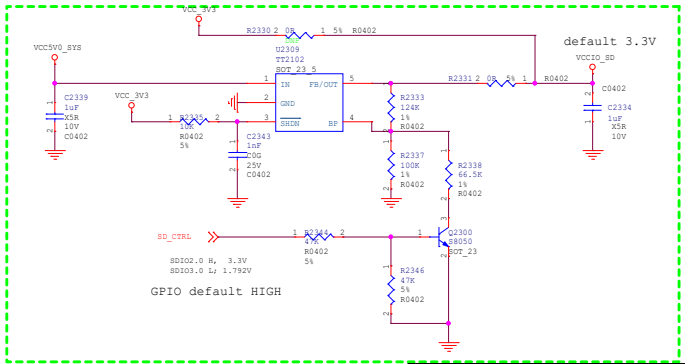
NOTE:
Recommend ETA3446 for better ripple.



VDD_LOG/NPU/VEPU power supply selection	R2314	R2316	R2317	R2360	Voltage range	NOTE
VDD_LOG/NPU/VEPU three-way merge	24K	12K	330K	0R	0.72V~0.88V	(1)
only VDD_NPU_VEPU is powered together	11K	24K	130K	NC	0.715V~0.975V	(2)

NOTE:
(1) Logic is combined with NPU and vepu:
the maximum voltage is only 0.88v, which makes the frequency of NPU not run very high.
It is only suitable for rv1109 and rv1126 without NPU high performance.

(2) Only NPU is combined with vepu:
It is only suitable for rv1109 and rv1126 .

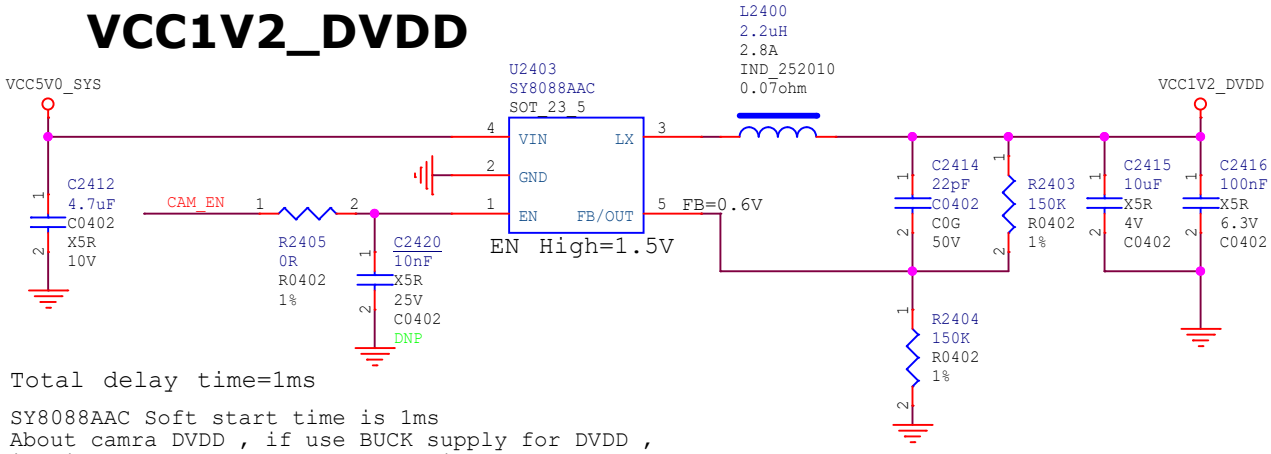


Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd
Project:	RV1126_RV1109 IPC REF
File:	23.Discrete Power for System
Date:	Friday, December 04, 2020
Rev:	V1.2
Designed by:	Yanhong.Li
Reviewed by:	<Checker>
Sheet:	21 of 44

Discrete Power for Camera

CAM_EN

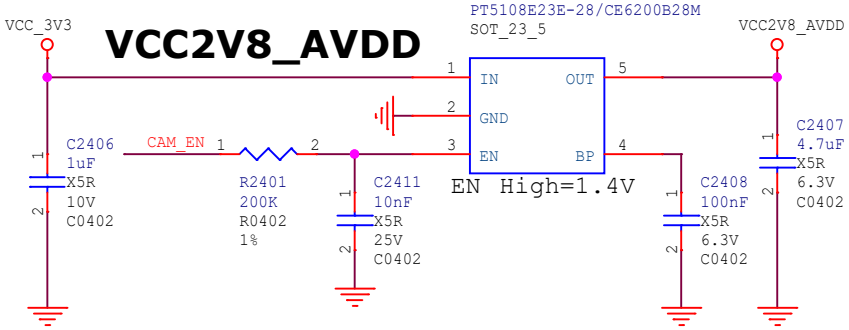
VCC1V2_DVDD



Total delay time=1ms

SY8088AAC Soft start time is 1ms
About camra DVDD , if use BUCK supply for DVDD ,
it will cost less power consumption.

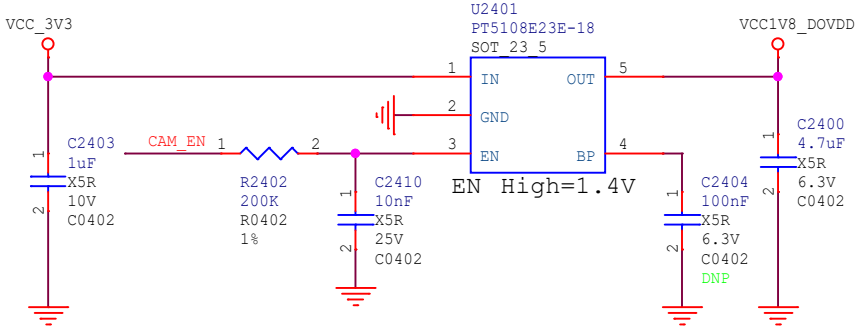
VCC2V8_AVDD



RC delay time=1.02ms

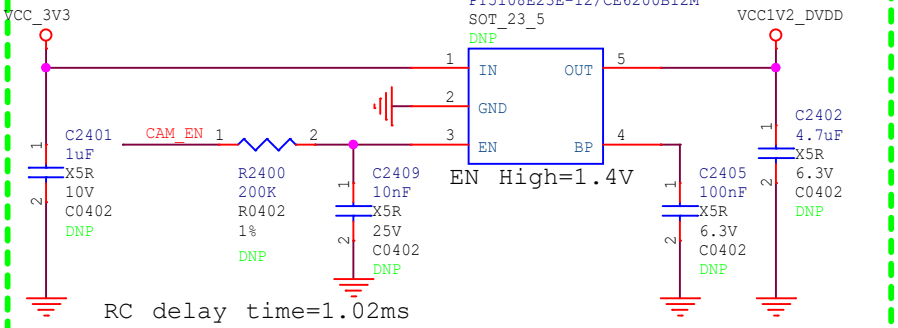
Total delay time=1ms

VCC1V8_DOVDD



RC delay time=1.02ms

Option: VCC1V2_DVDD

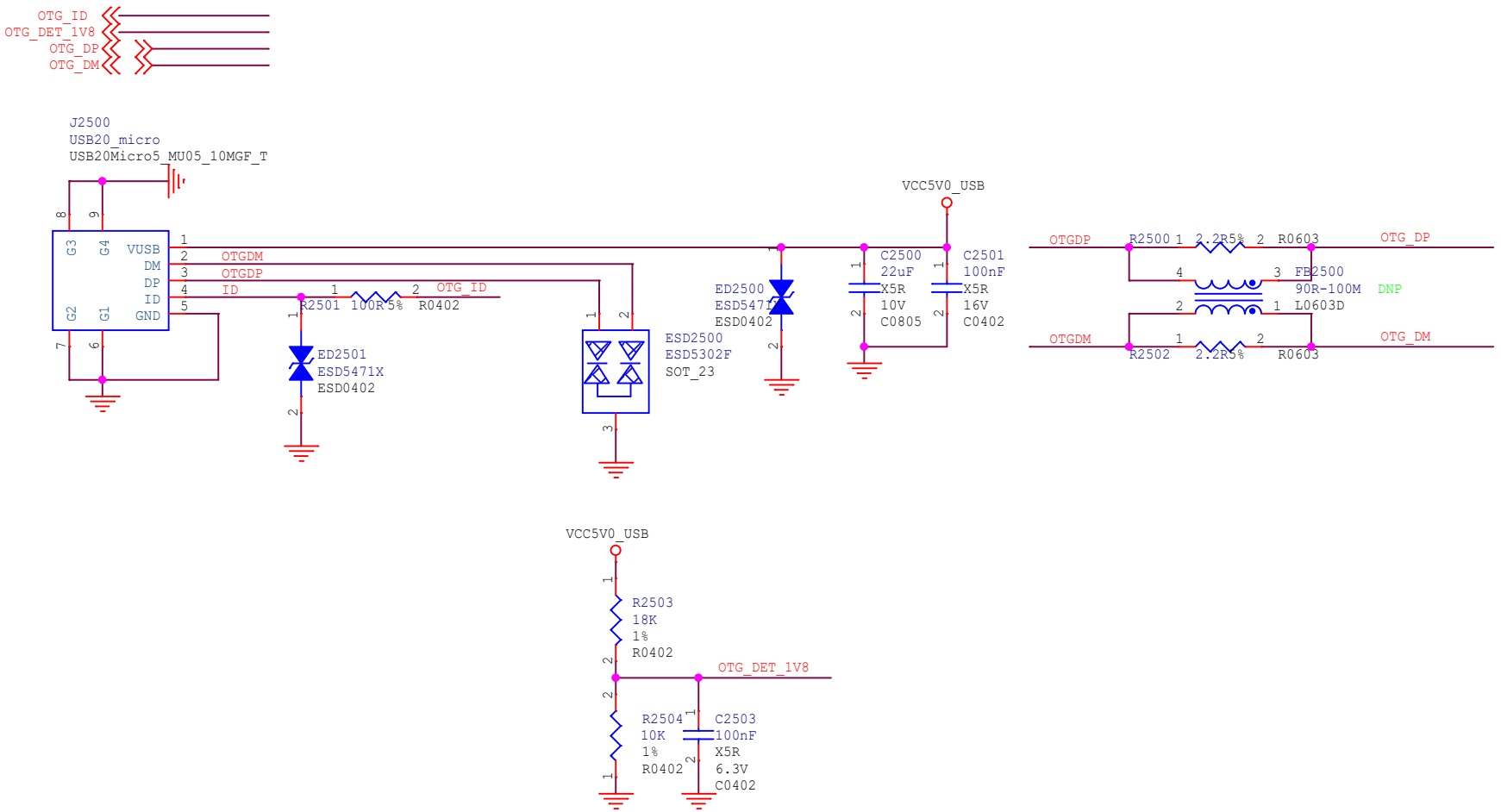


RC delay time=1.02ms

NOTE:
It's recommended to use DCDC for the DVDD and AVDD of camera for saving power consumption of battery solution.

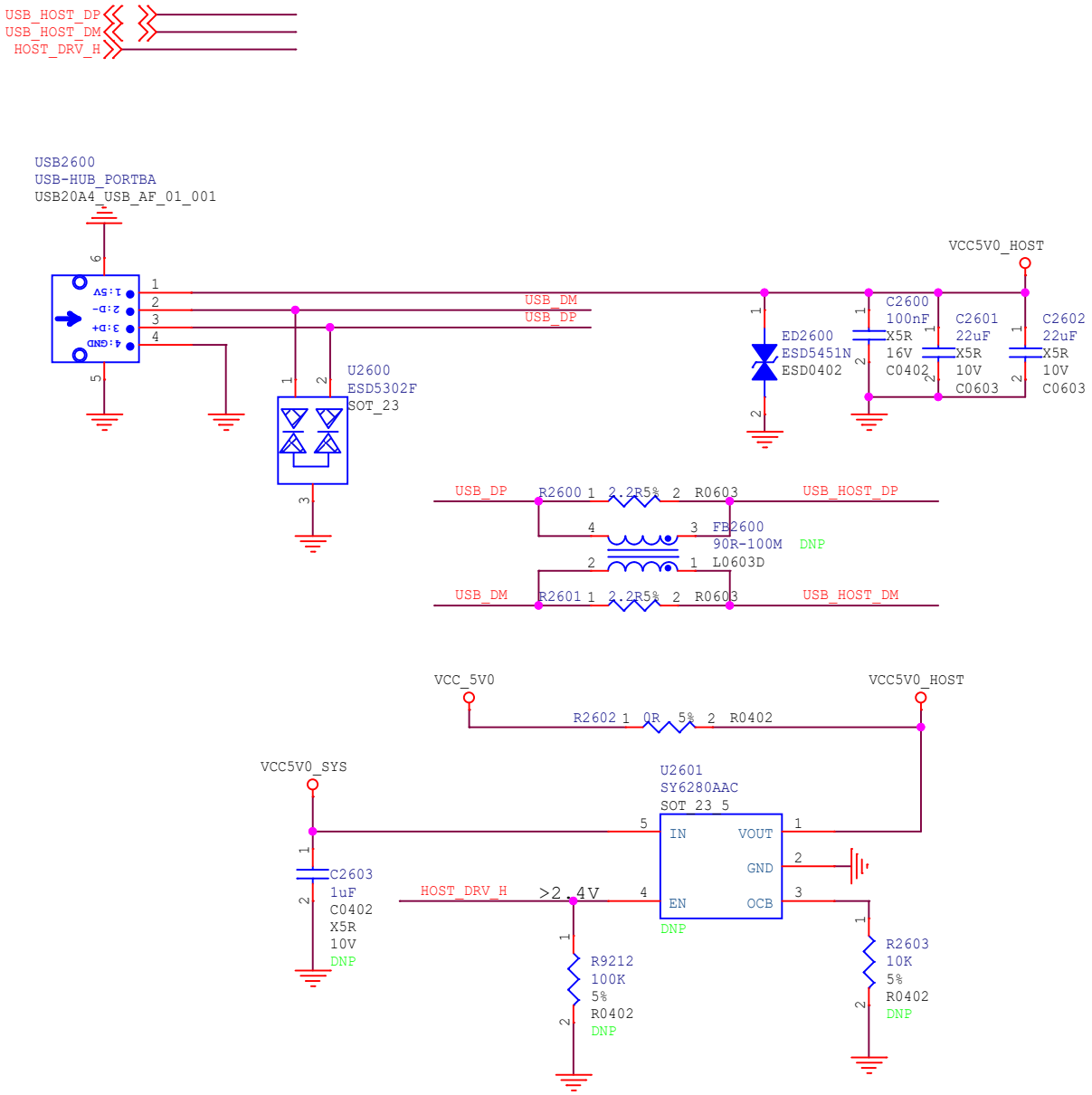
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	24.Discrete Power for Camera				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	22 of 44

USB2.0 OTG



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	25.USB OTG				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	23 of 44

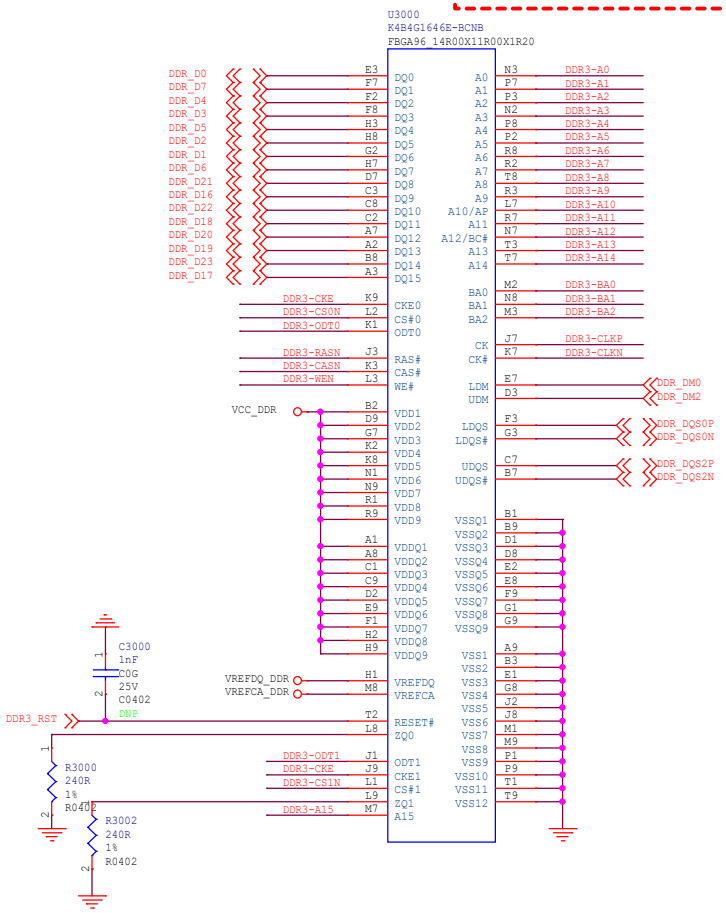
USB HOST

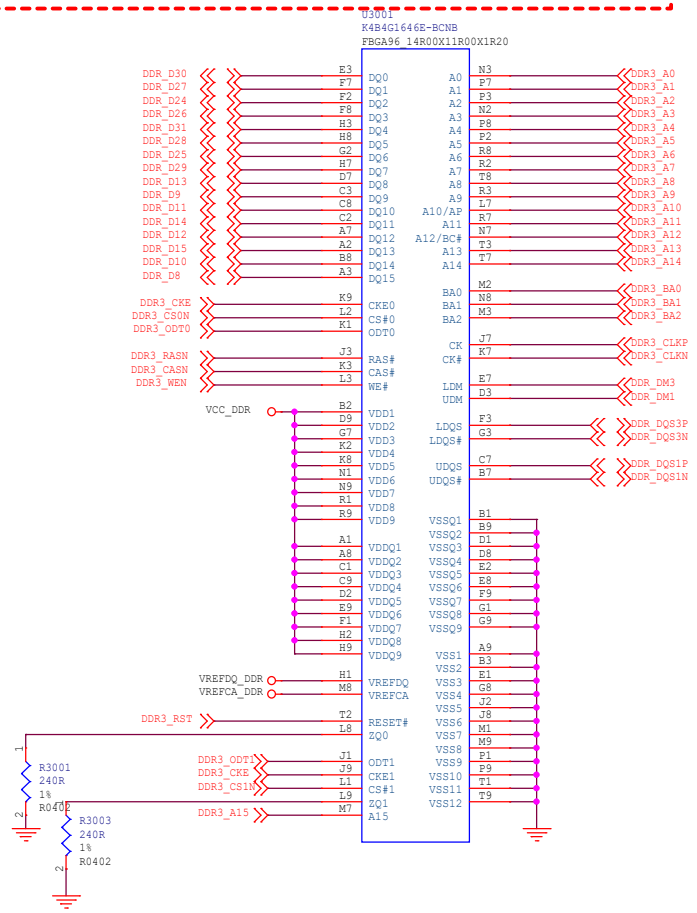


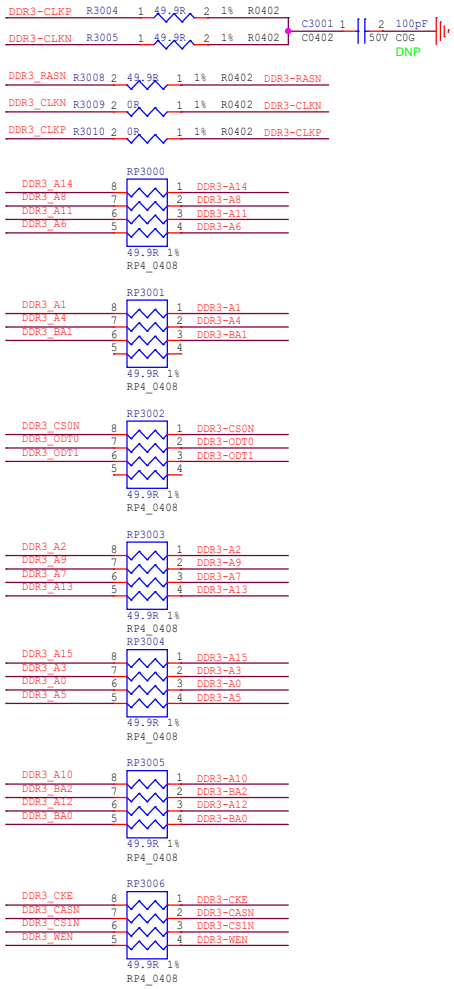
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	26.USB Host				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	24 of 44

DDR3/DDR3L 2x16bit

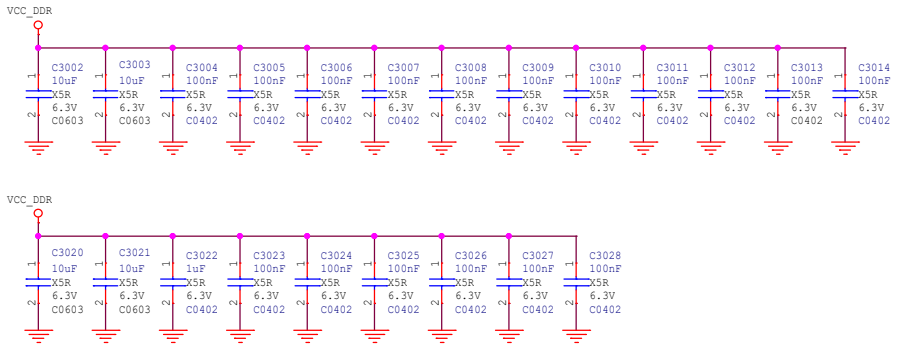
Note:
This is DDR template<RV1126_RV1109_Template_DDR3P216SD4_V10_20200619>. 4 layers PCB.
If only need one pcs DDR, please must use U3000(lane0,lane2).
If need other template, please apply to RK.

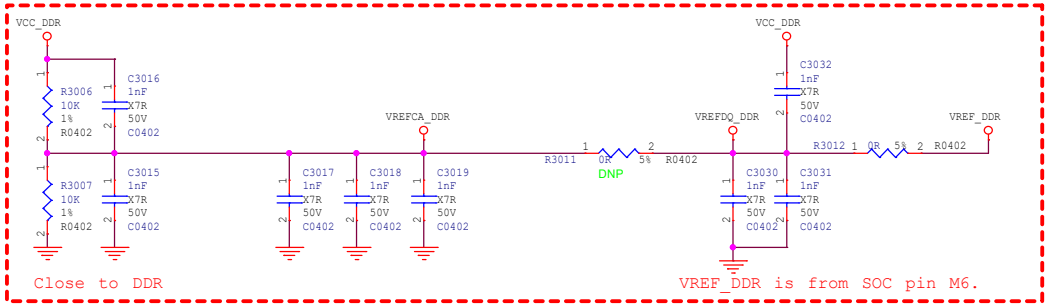






Note:All the Power filter capacitors should be placed close to the power pins of DDR3





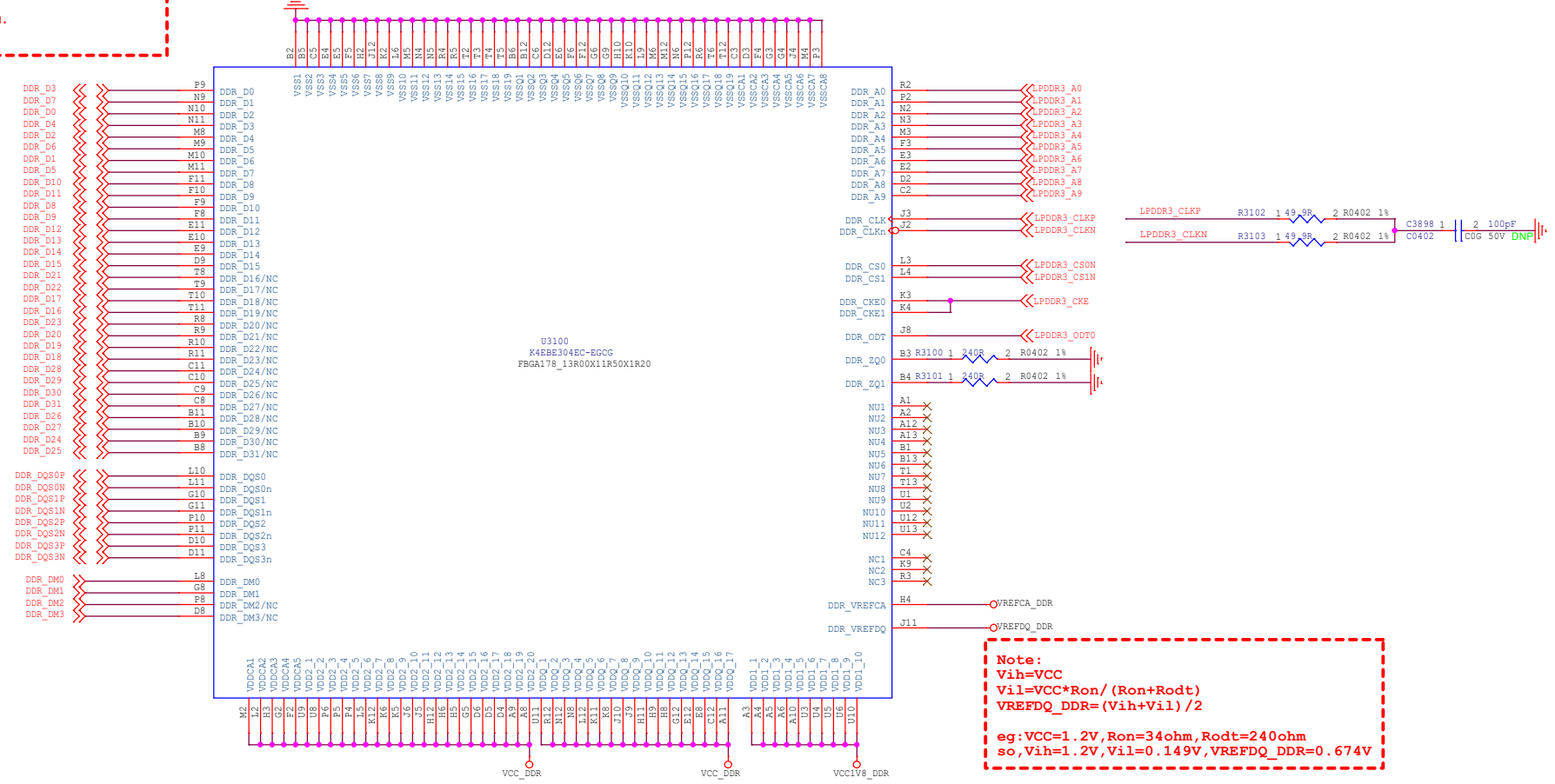
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	30.DRAM_DDR3_96P_2X16bit				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	25 of 44

LPDDR3 1x32bit

NOTE:
The sequence of DQ shall be done according to the template and shall not be adjusted or changed

Refer to the latest AVL for parts selection.

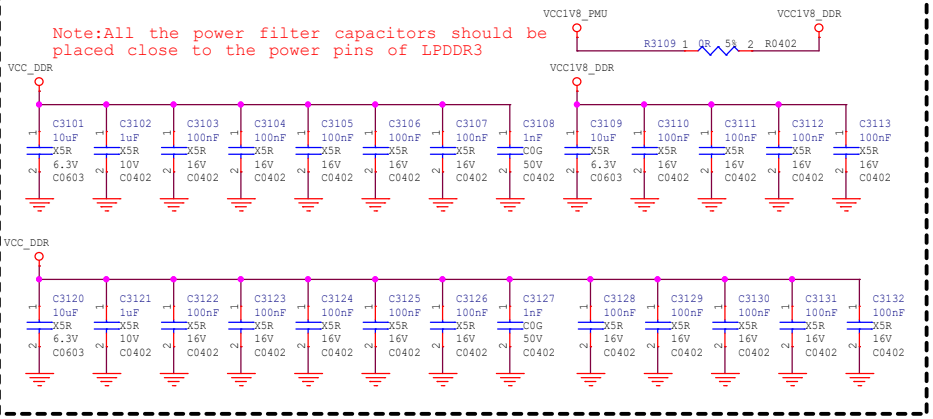
Note:
This is DDR template<RV1126_RV1109_Template_LP3S178P132SD6_V10_20200325>. Six layers PCB.

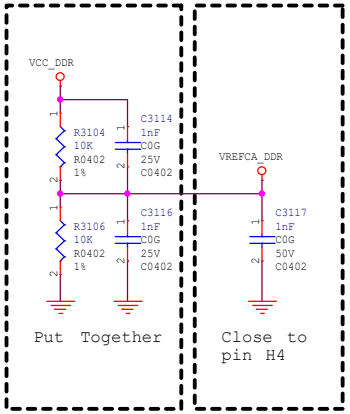


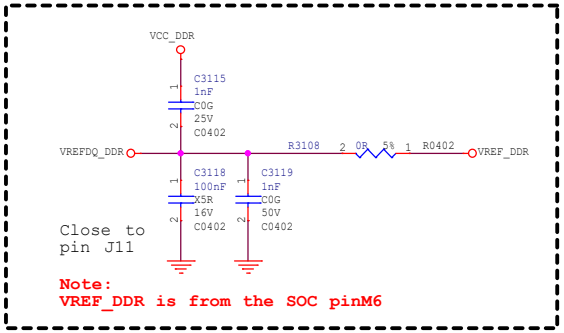
Note:
Vih=VCC
Vil=VCC*Ron/(Ron+Rodt)
VREFDQ_DDR=(Vih+Vil)/2

eg:VCC=1.2V,Ron=34ohm,Rodt=240ohm
so,Vih=1.2V,Vil=0.149V,VREFDQ_DDR=0.674V

Note:All the power filter capacitors should be placed close to the power pins of LPDDR3





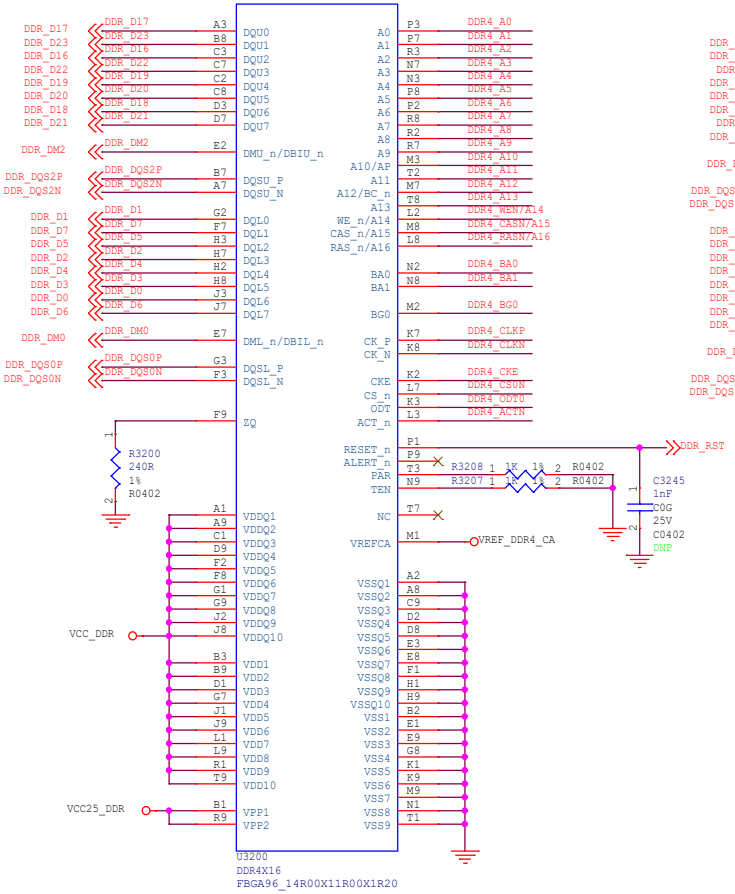


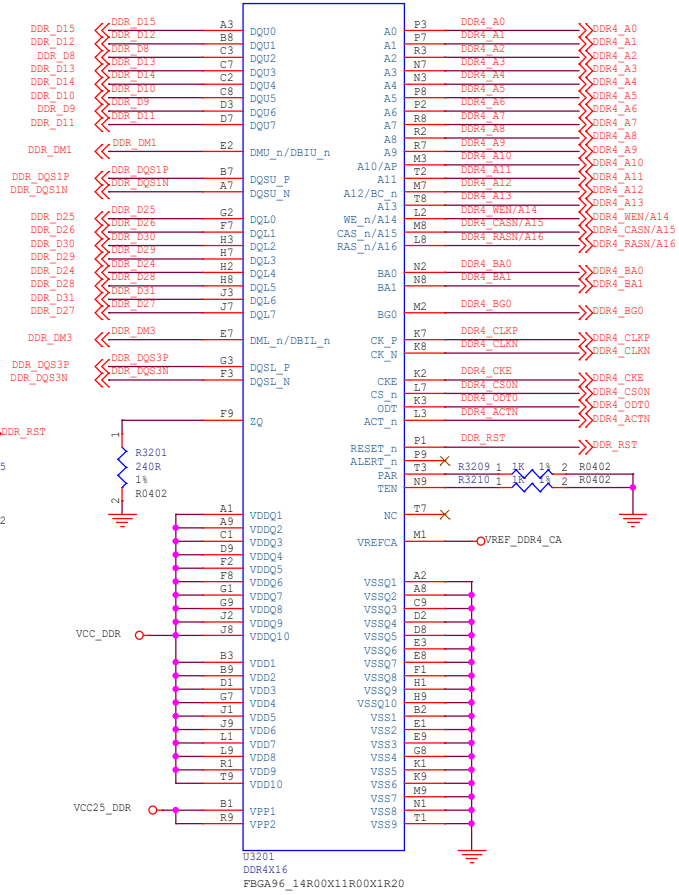
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	31. DRAM_LPDDR3_32 bit				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	26 of 44

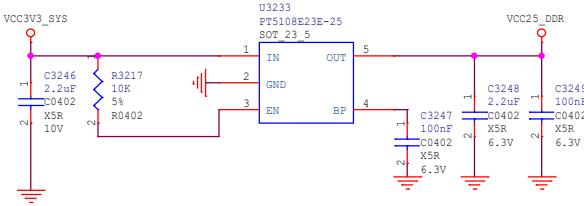
DDR4 2x16bit

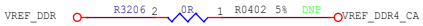
NOTE:
The sequence of DQ shall be done according to the template and shall not be adjusted or changed
Refer to the latest AVL for parts selection.

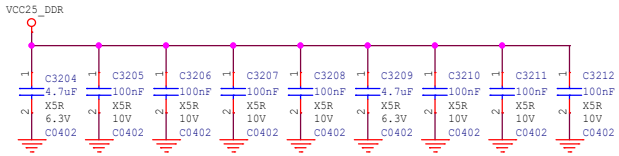
Note:
This is DDR template<RV1126_RV1109_Template_DDR4P216DD6_V10_20200325>.Six layers PCB.
If only need one pcs DDR, please must use U3200(lane0,lane2).

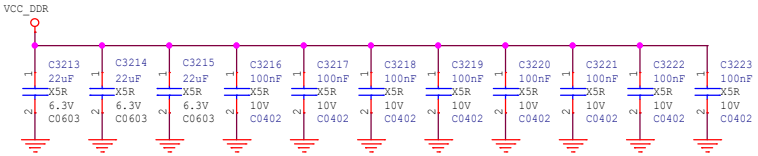


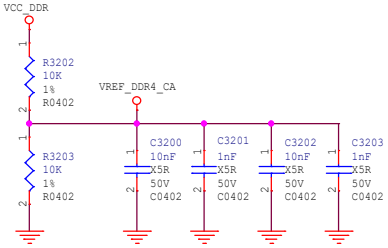


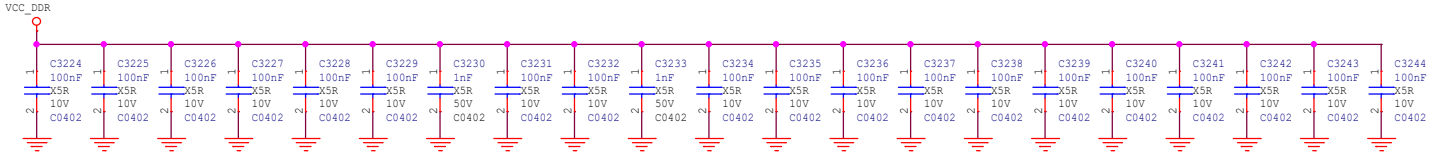










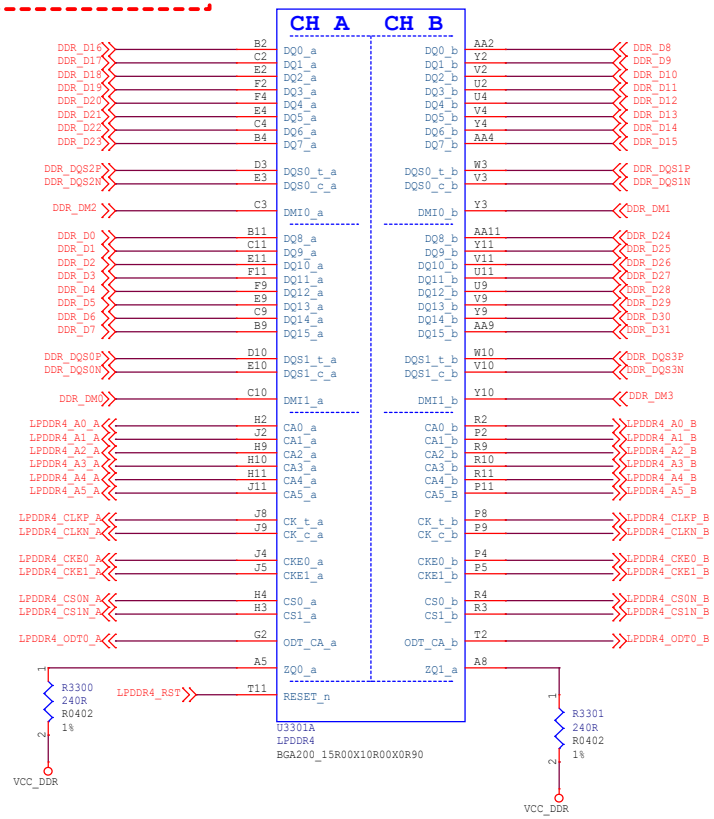


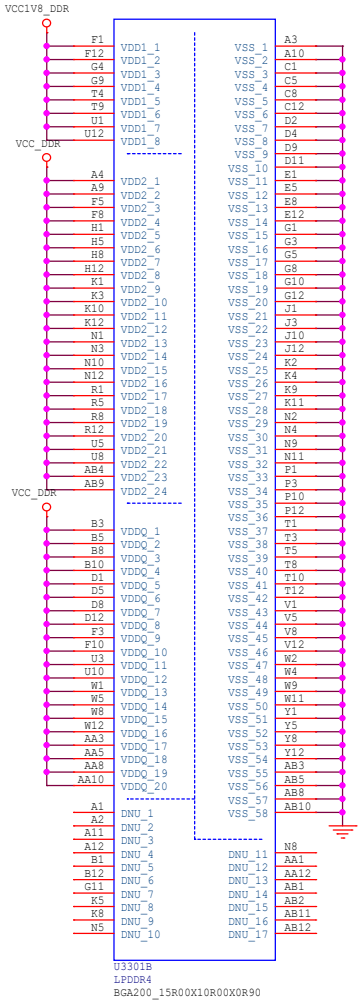
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	31. DRAM_LPDDR3_32 bit				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	27 of 44

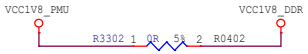
LPDDR4 1x32bit

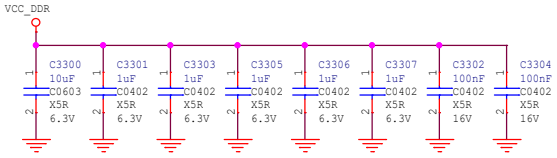
NOTE:
The sequence of DQ shall be done according to the template and shall not be adjusted or changed
Refer to the latest AVL for parts selection.

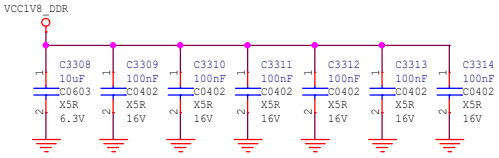
Note:
This is DDR template<RV1126_RV1109_Template_LP4S200P132SD6>. Six layers PCB.
If only need one pcs DDR, please must use U3200(lane0,lane2).

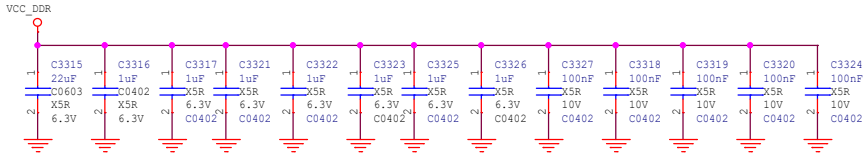








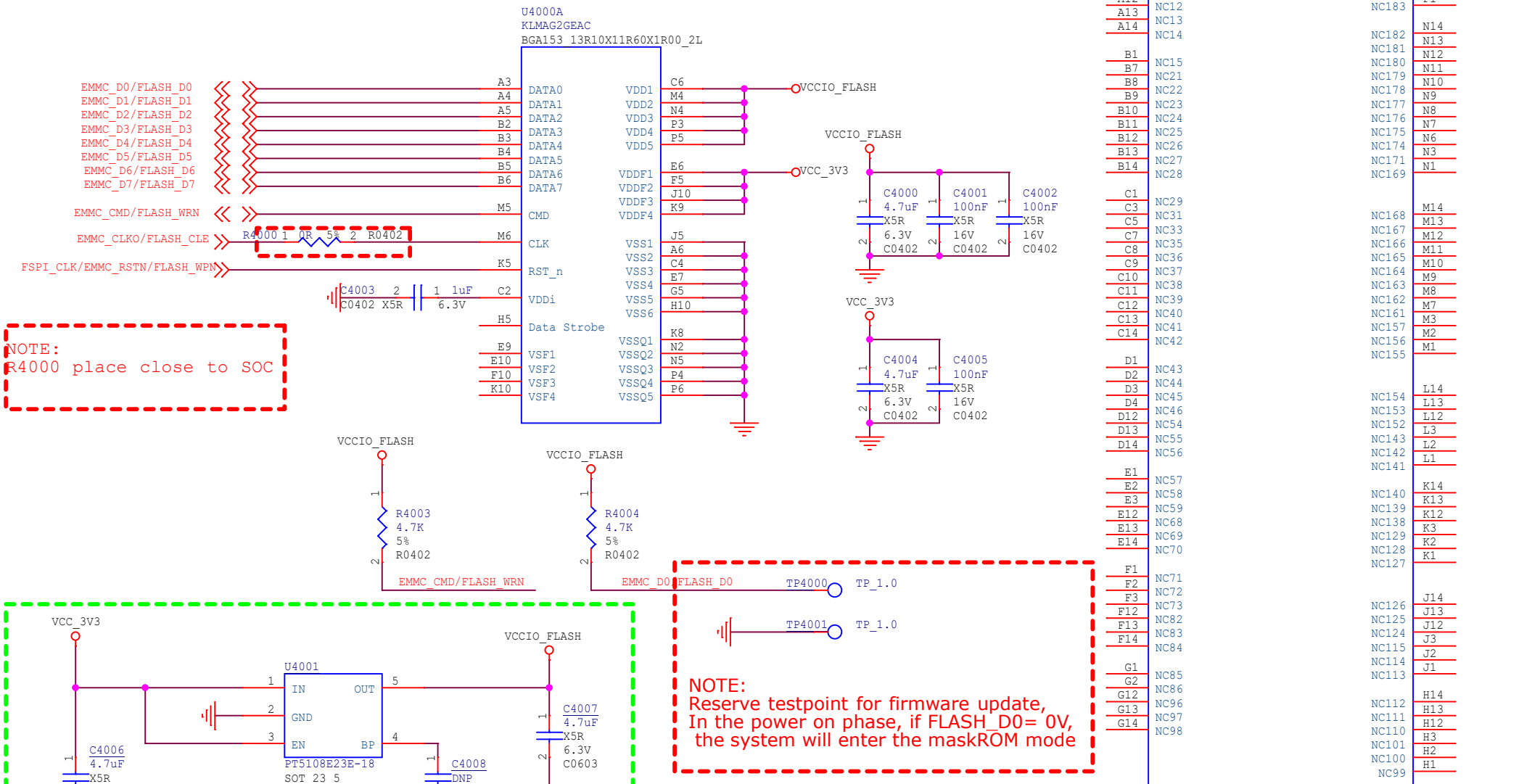




Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	33.DRAM_LPDDR4_32 bit				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	28 of 44

eMMC

NOTE:
Refer to the latest AVL for parts selection.
NOTE:
All the power filter capacitors should be placed close to the power pins of SOC.



NOTE:
R4000 place close to SOC

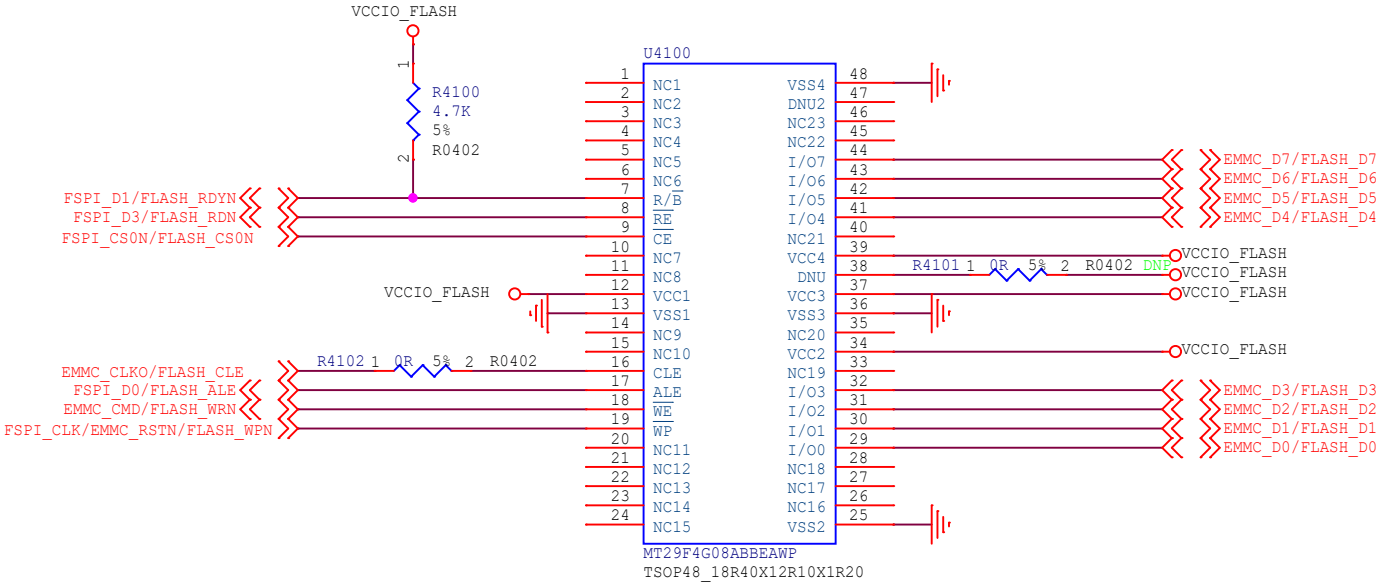
OPTION:
If EMMC peak current > 300mA,
please use LDO supply

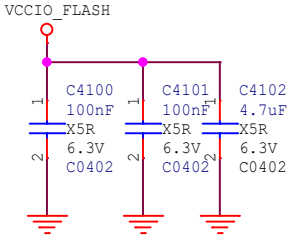
NOTE:
Reserve testpoint for firmware update,
In the power on phase, if FLASH_D0= 0V,
the system will enter the maskROM mode

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	40.Flash-eMMC Flash				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	29 of 44

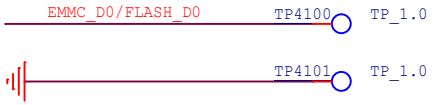
NAND FLASH

NOTE:
Refer to the latest AVL for parts selection.
Only support SLC NAND





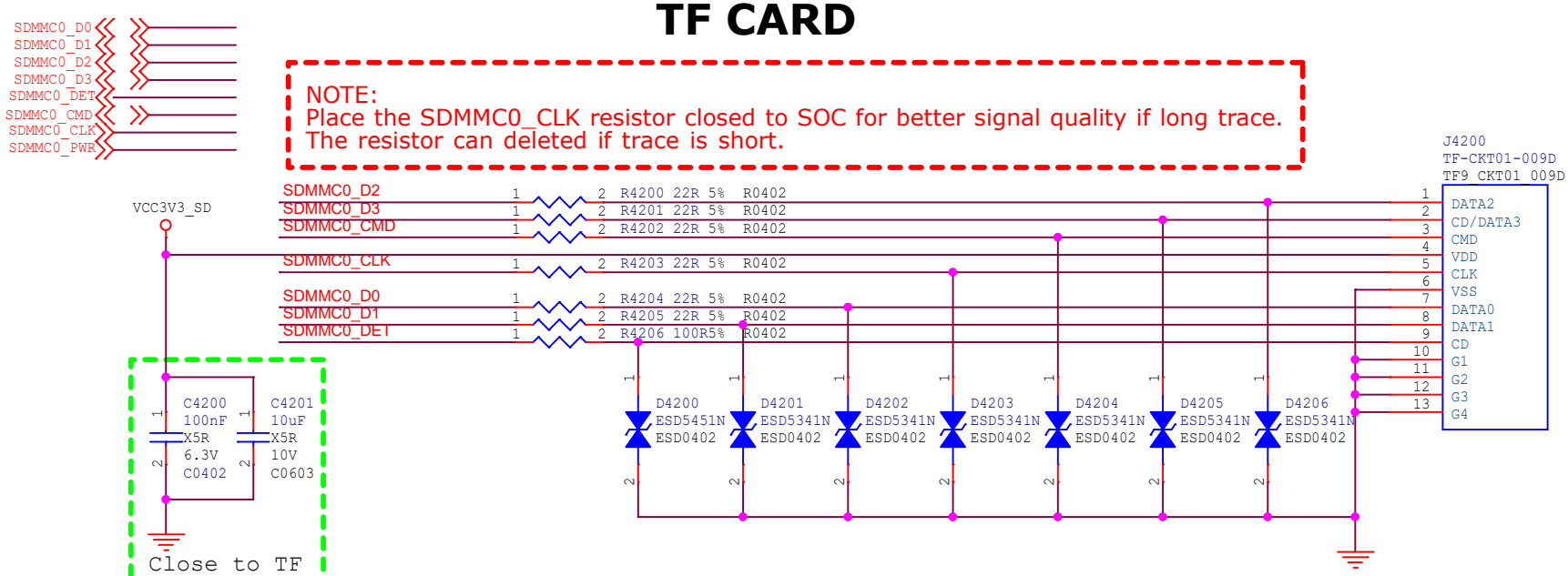
NOTE:
All the power filter capacitors should be placed close to the power pins of SOC.

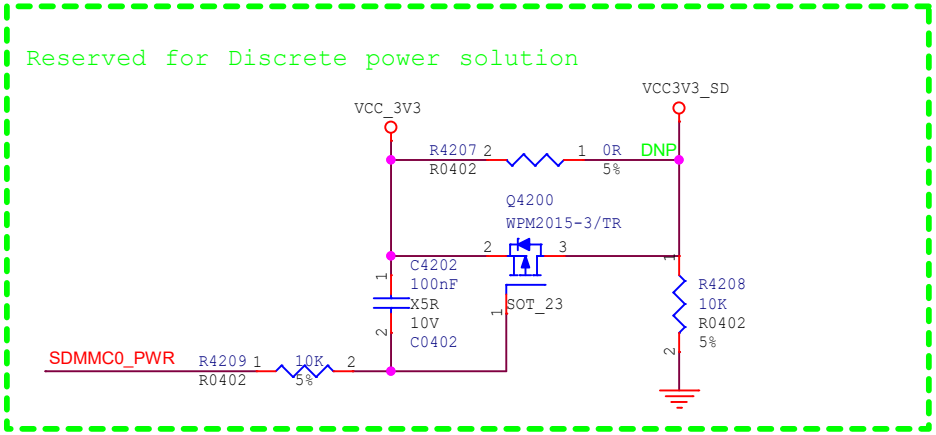


NOTE:
Reserve testpoint for firmware update,
In the power on phase, if FLASH_D0= 0V,
the system will enter the maskROM mode

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	41.Flash-Nand Flash				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	30 of 44

TF CARD

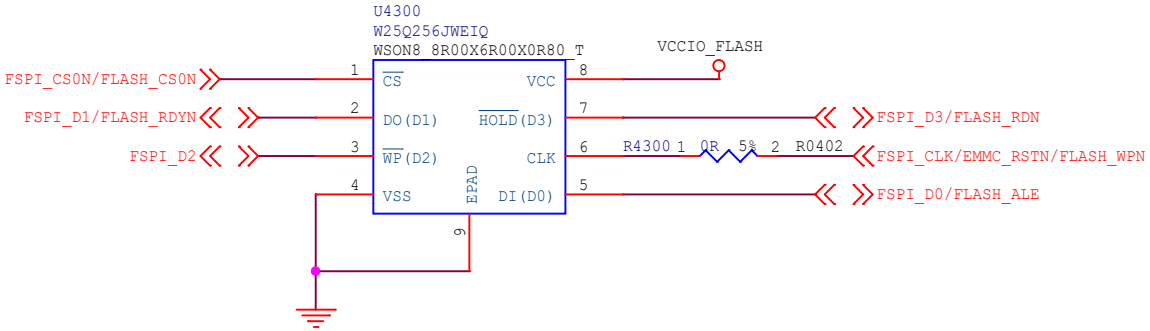


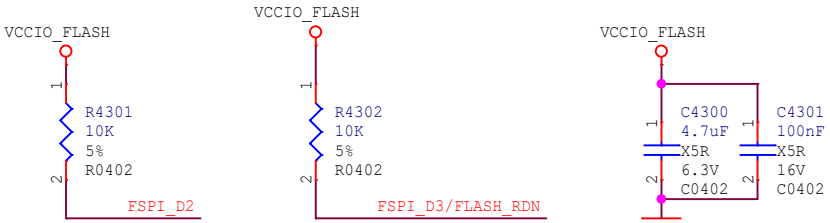


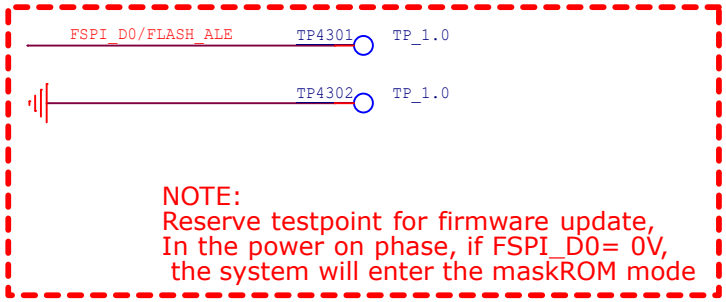
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	42.Flash-Micro-SD Card				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	31 of 44

SPI_Flash

NOTE:
Refer to the latest AVL for parts selection.

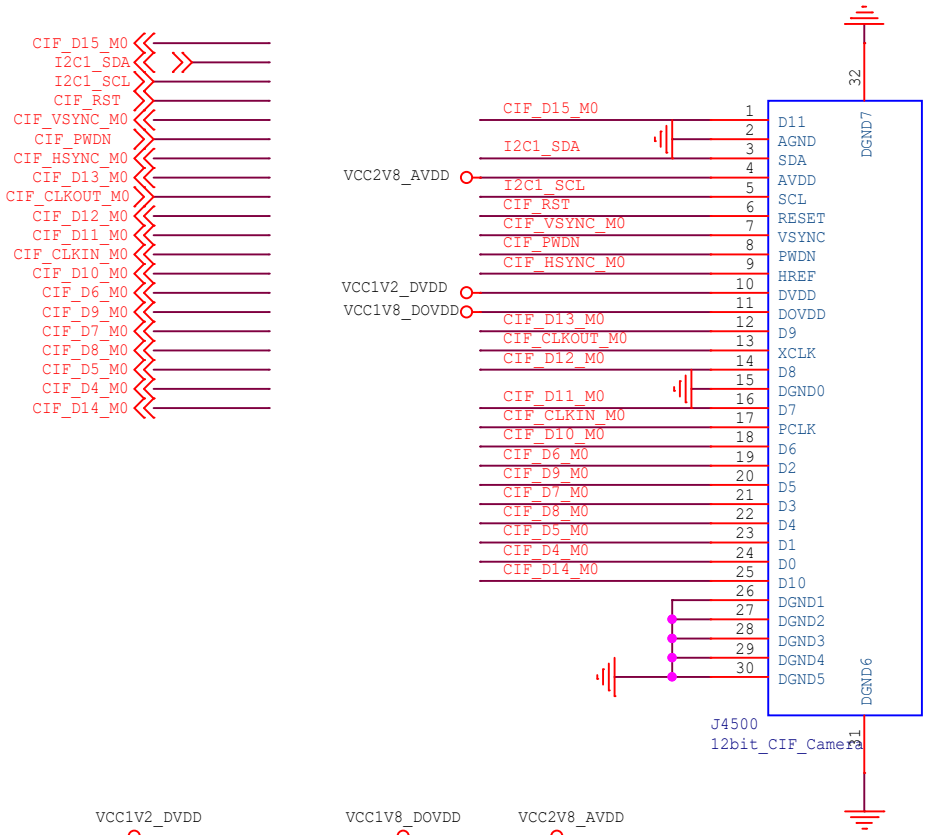






Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	43.Flash-SPI Flash				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	32 of 44

CIF Camera Interface



Correspondence CIF data and BT1120/12bit/10bit/8bit CIF				
16bit CIF data	BT1120	12bit CIF camera	10bit CIF camera	8bit CIF camera
CIF_D0	BT1120_D0			
CIF_D1	BT1120_D1			
CIF_D2	BT1120_D2			
CIF_D3	BT1120_D3			
CIF_D4	BT1120_D4	D0		
CIF_D5	BT1120_D5	D1		
CIF_D6	BT1120_D6	D2	D0	
CIF_D7	BT1120_D7	D3	D1	
CIF_D8	BT1120_D8	D4	D2	D0
CIF_D9	BT1120_D9	D5	D3	D1
CIF_D10	BT1120_D10	D6	D4	D2
CIF_D11	BT1120_D11	D7	D5	D3
CIF_D12	BT1120_D12	D8	D6	D4
CIF_D13	BT1120_D13	D9	D7	D5
CIF_D14	BT1120_D14	D10	D8	D6
CIF_D15	BT1120_D15	D11	D9	D7

NOTE:
According to the current of the actual camera module, evaluate whether the current output by LDO can meet the requirement of two cameras using at the same time. If not, please add LDO to supply power

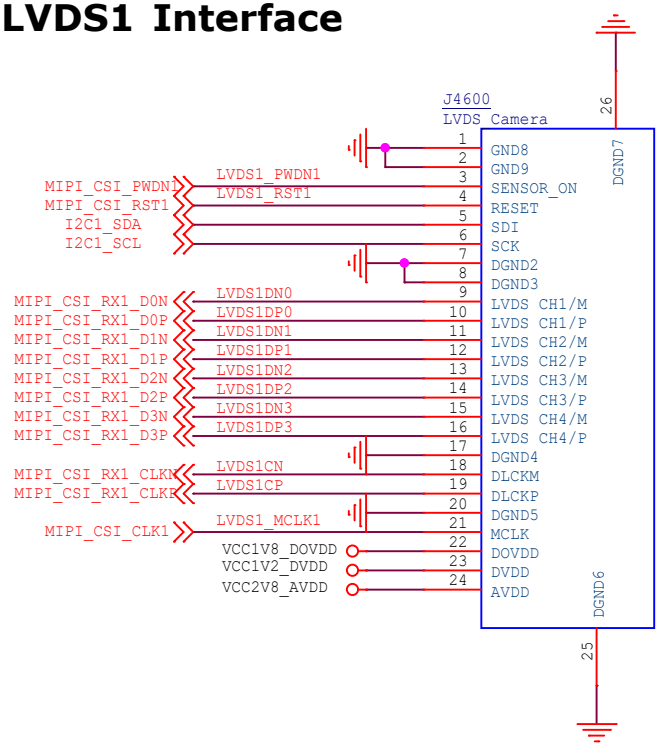
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	45.VI-Camera_CIF				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	33 of 44

OPTION: LVDS Interface
LVDS interface and mipicsi interface share pins,
only one of them can be selected at a time

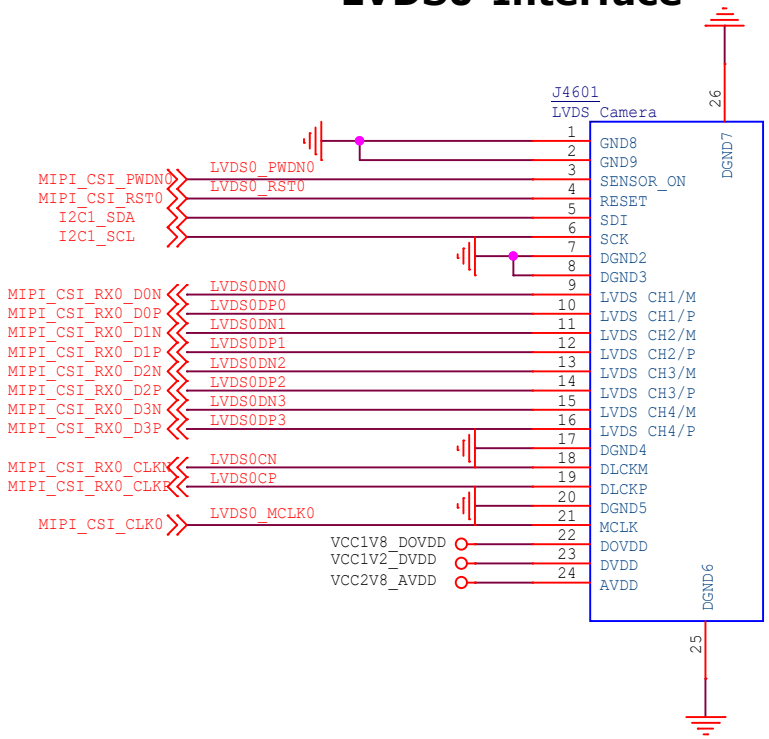
NOTE:
1) According to the current of the actual camera module, evaluate whether the current output by LDO can meet the requirement of two cameras using at the same time. If not, please add LDO to supply power.

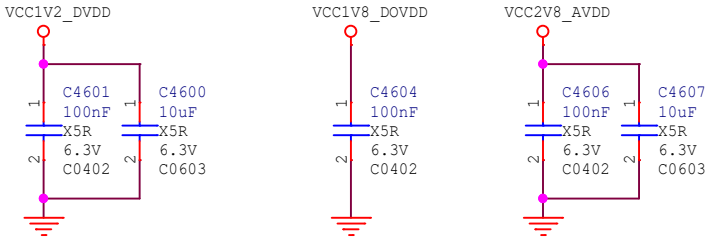
2) Imx307, imx327 sensors must use LVDS interface, and use 4 lanes, HDR frame rate can meet the requirements

LVDS1 Interface



LVDS0 Interface



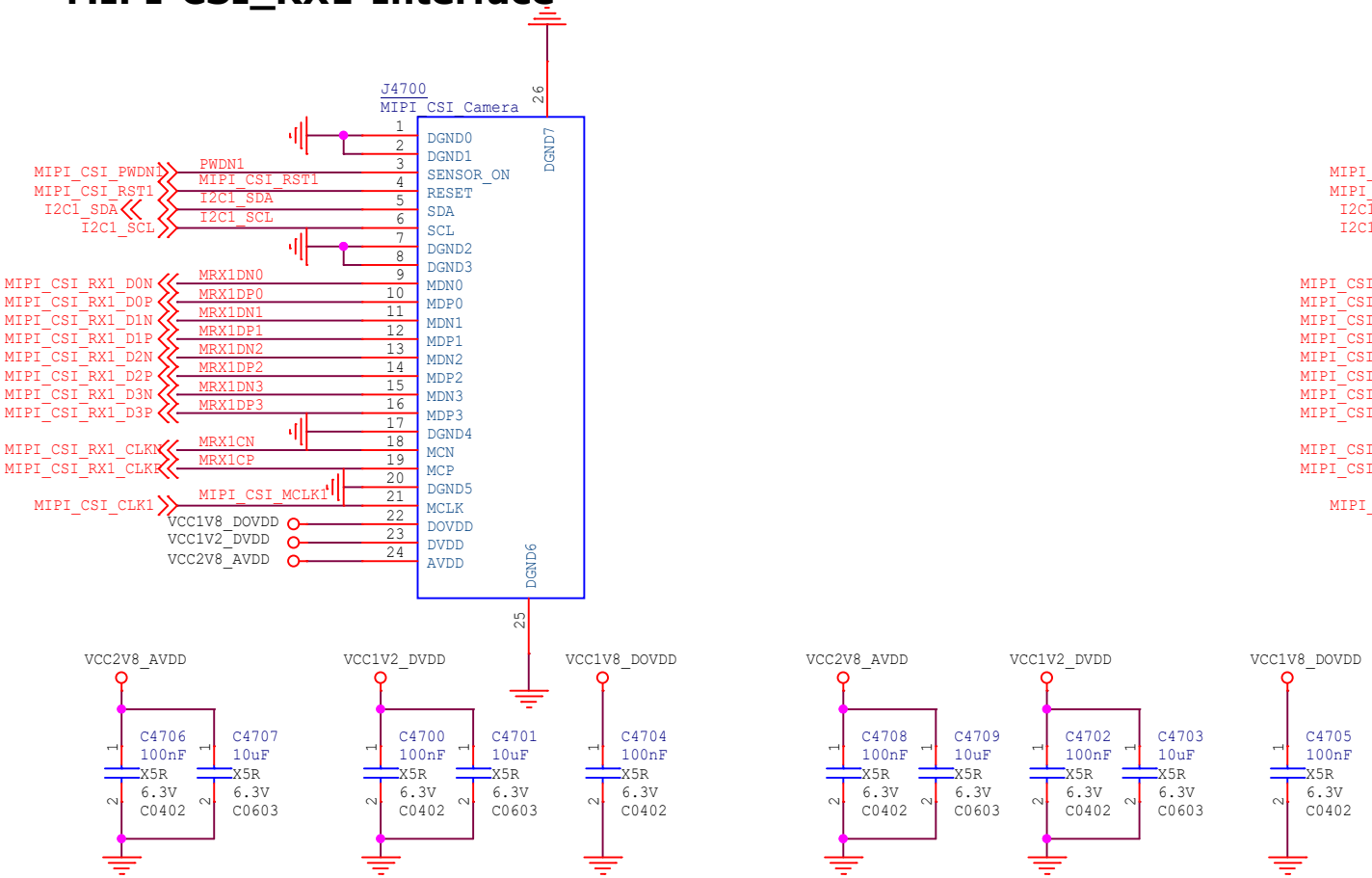


Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	46.LVDS/Sub-LVDS Camera(option)				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	34 of 44

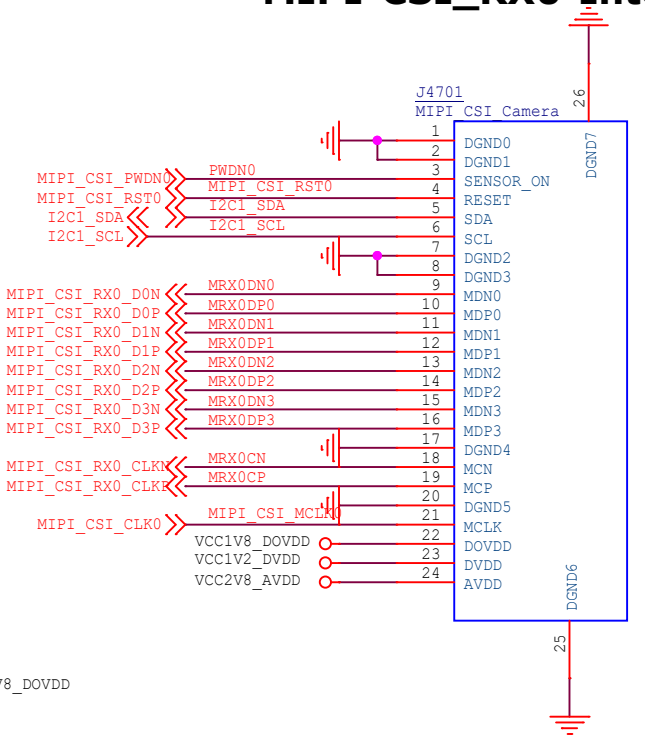
DEFAULT: MIPI_CSI Interface
LVDS interface and mipicsi interface share pins,
only one of them can be selected at a time.

NOTE:
1) According to the current of the actual camera module, evaluate whether the current output by LDO can meet the requirement of two cameras using at the same time.
2) If not, please add LDO to supply power.
3) If the I2C addresses of the two cameras are the same, use another set of I2C.
4) Imx307, imx327 sensors must use LVDS interface, and use 4 lanes, HDR frame rate can meet the requirements

MIPI-CSI_RX1 Interface

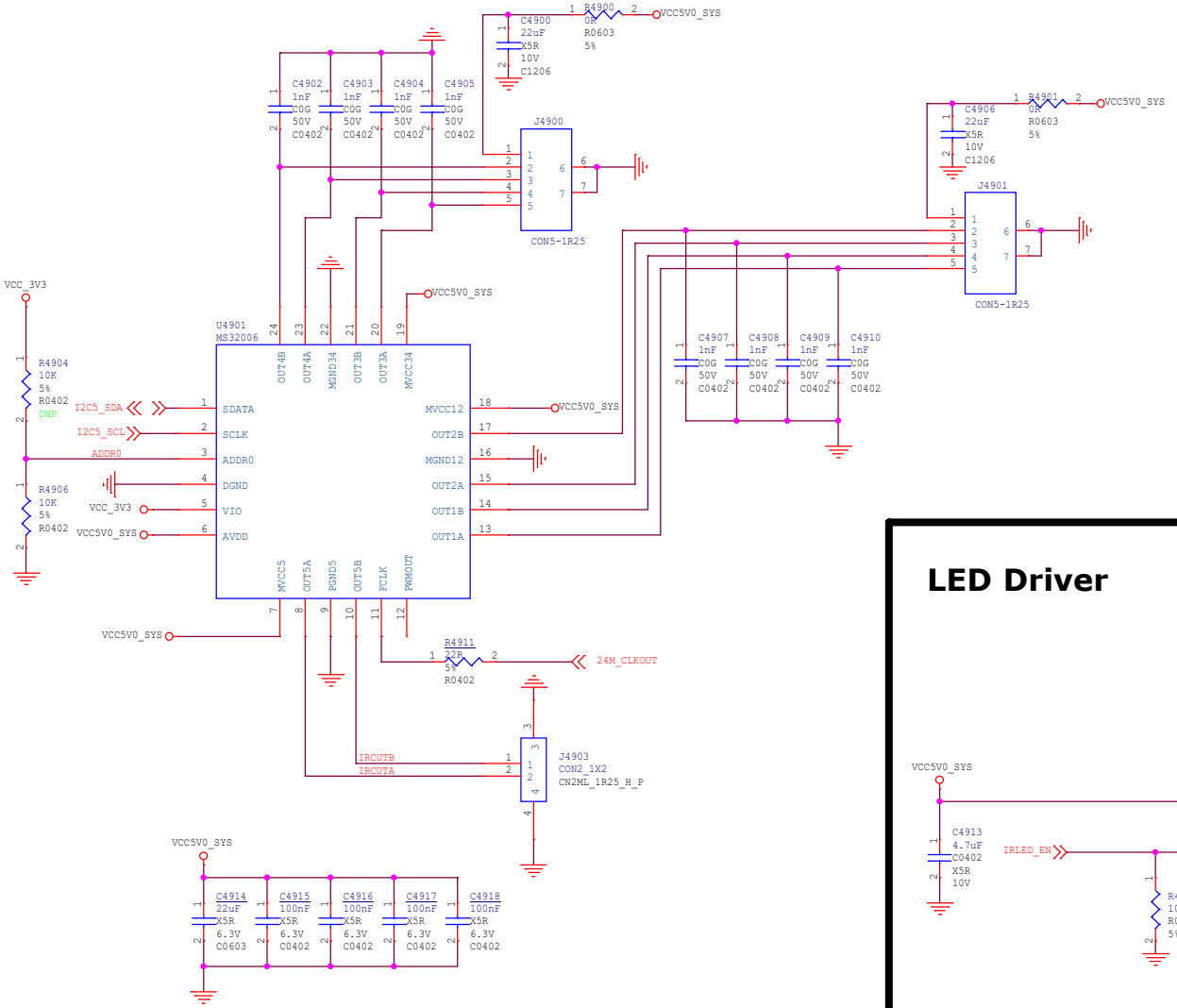


MIPI-CSI_RX0 Interface

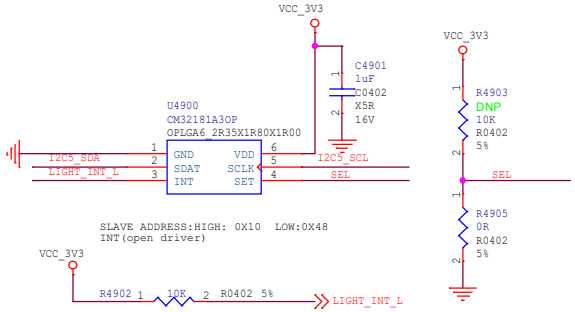


Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	47.VI-Camera_MIPI-CSI				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	35 of 44

IR Cut Driver PAN/TILT Driver

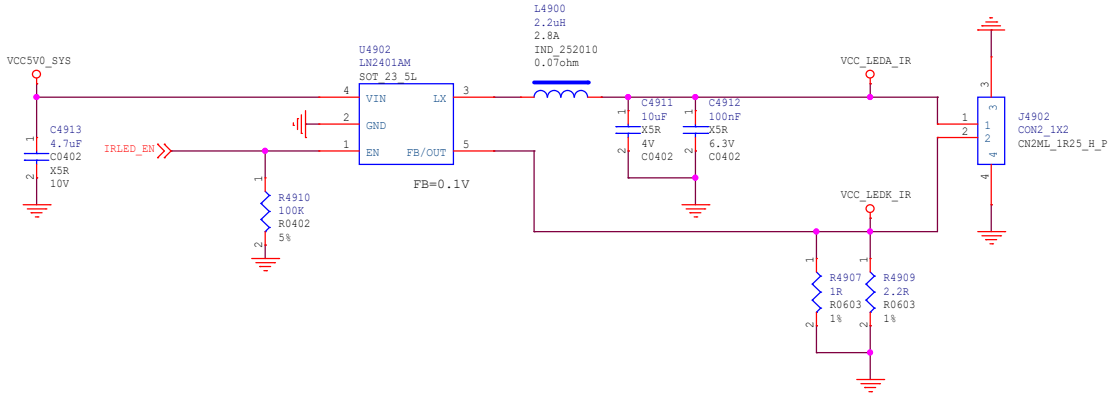


Light Sensor



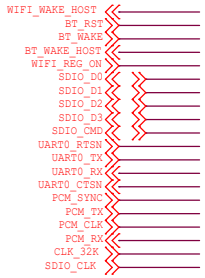
LED Driver

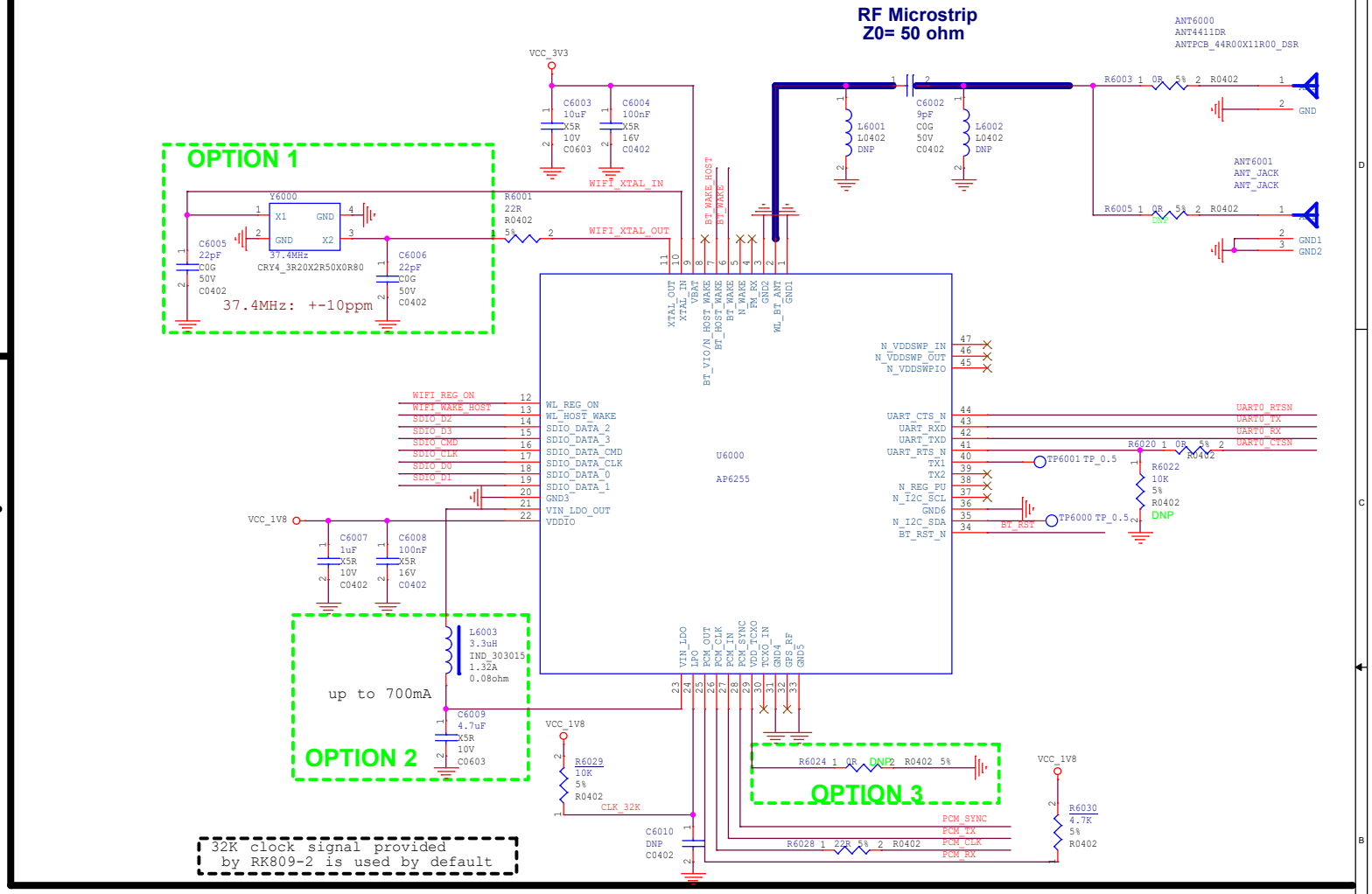
850nm Vrf=1.3V



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	49.IRC/Motor Driver				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	36 of 44

WIFI/BT Module





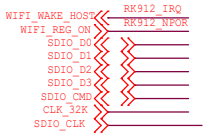
WIFI module		
Pin	AP6255	UWE5622
6	BT_WAKE	CHIP EN
7	BT_HOST_WAKE	AP_INT
12	WL_REG_ON	RST_N
13	WL_HOST_WAKE	SD_INT

Note:
Yes: option circuit be mounted
No: option circuit not be mounted

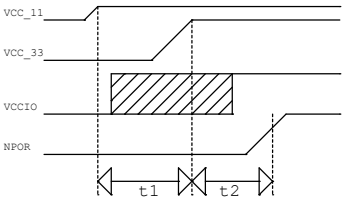
OPTION	WIFI				BT	Crystals	VCCIO_SDIO	OPTION1	OPTION2	OPTION3
	a	b/g/n	ac	5GHz						
AW-CM256SM	Yes	Yes	Yes	Yes	4.2	37.4MHz	1.71-3.63V	Yes	Yes	Yes@SDIO2.0 No@SDIO3.0
AP6236/AP6212	No	Yes	No	No	4.2/4.0	26MHz	1.71-3.63V	Yes	Yes	No
AP6256/AP6255	Yes	Yes	Yes	Yes	5.0/4.2	37.4MHz	1.62-3.63V	Yes	Yes	Yes@SDIO2.0 No@SDIO3.0
RTL8189FTV Module F89FTSM12-W3	No	Yes	No	No	No	Module Integrated	1.8-3.3V	No	No	No
RTL8723DS Module 6223A-SRD	No	Yes	No	No	4.2	Module Integrated	1.62-3.63V	No	No	No
QCA9377 Module 8223A-SR	Yes	Yes	Yes	Yes	4.2	Module Integrated	1.7-3.45V	No	No	No
RTL8821CS Module 6221A-SRC	Yes	Yes	Yes	Yes	4.2	Module Integrated	1.7-3.45V	No	No	No
UWE5622	Yes	Yes	Yes	Yes	5.0	Module Integrated	1.62-1.98V	No	No	No

Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	60.WIFI/BT-SDIO_1T1R+UART				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	37 of 44

WIFI RK912



Power Sequence



t1>=1ms, t2>=1ms

Power Consumption

State	VCCIO	VCC_33	VCC_11
Sleep	0.1mA	0.1mA	0.1mA
PowerSave(DTIM=1)	0.1mA	2.6mA	1.3mA
TX(11b 11M)	0.8mA	192mA	15.6mA
TX(11g 54M)	0.8mA	169.5mA	16.3mA
TX(11n 65M)	0.8mA	168.6mA	16.4mA
RX(11n 65M)	0.8mA	42.9mA	21.3mA

Note: All data test under continue mode
VCCIO test under 3.3V

RF Routing

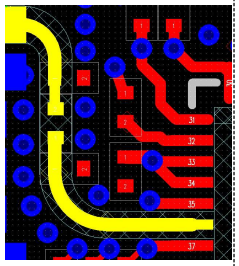
Short and smooth routing with 50 ohm

No layer change, top layer best

Place GND via along RF trace

Integral reference GND for RF trace

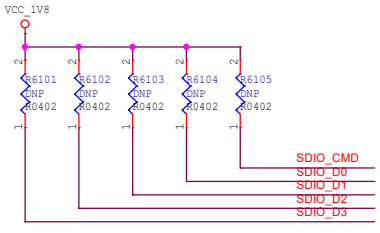
Excavate L2 on RFIO pin and antenna pad



Other Routing Requirement

SDIO CLK trace must be surounded by GND
Do not split L2 GND layer
Epad connet to GND by via alone, minimum 16 via
Pin 4/7/14/18 connet GND by seperate via best

Optional



Note: Reserve pull-high resistors for SDIO data pins base on platform

Crystal Requirement

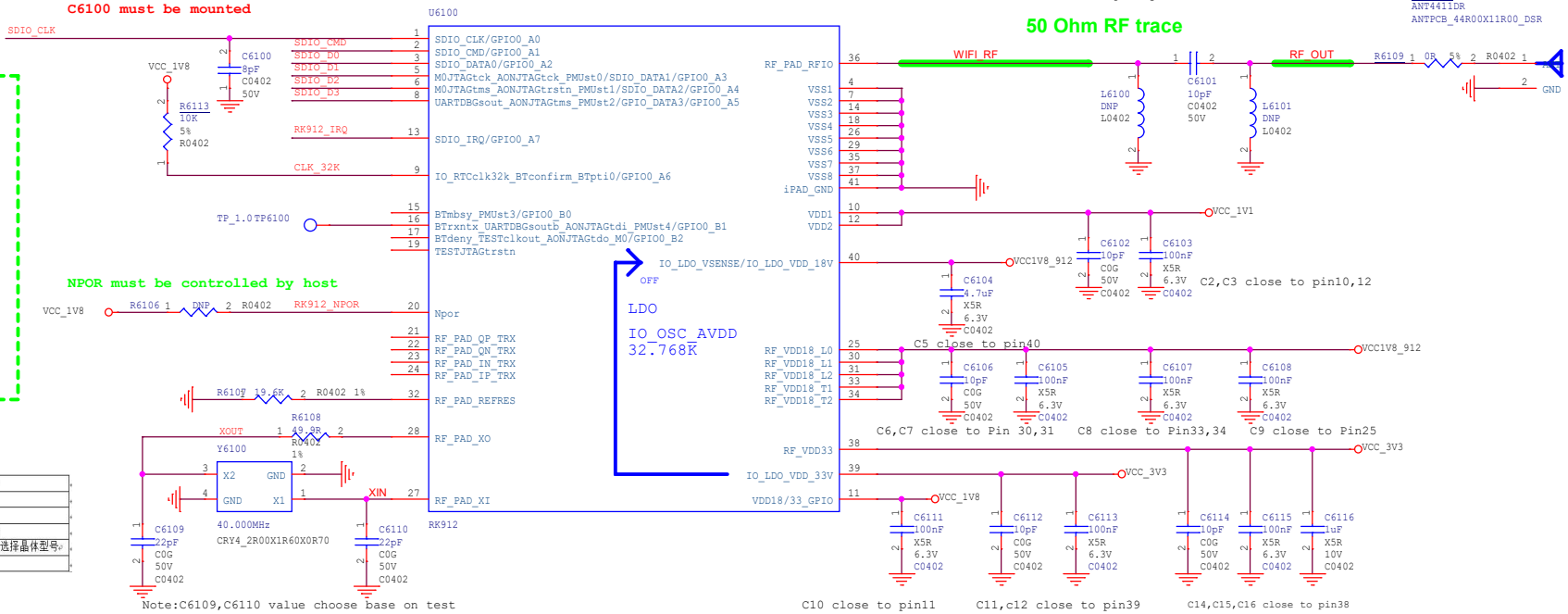
参数	规范			描述
	最小	最大	单位	
频率	40.000000		MHz	
频率偏差	+/-10		ppm	Frequency tolerance
工作温度	-20	80	℃	根据实际产品温度需求选择晶体型号
ESR	/	60	Ohm	

Crystal Routing

Close to RK912
Trace surround by GND
Other signal trace prohibited under crystal

C6100 must be mounted

NPOR must be controlled by host



Note:C6109,C6110 value choose base on test

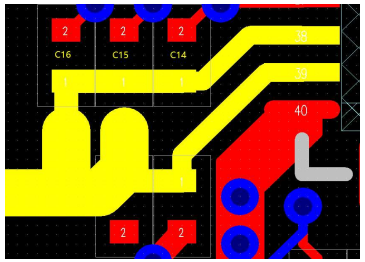
Reserve matching component location for antenna

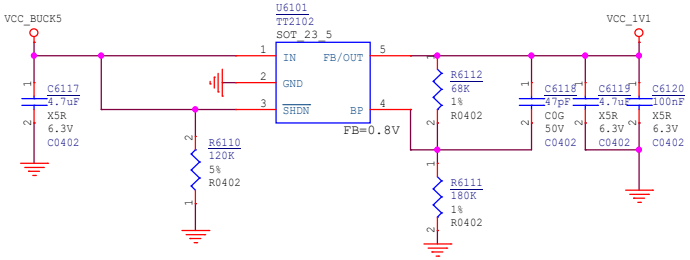
50 Ohm RF trace

ANT6100
ANT441IDR
ANTPCB_44R00X11R00_DSR

Power Routing

Power trace follow star routing
Samll value capacitor closer to pin
10pF closest to pin, then 100nF,
then 1uF



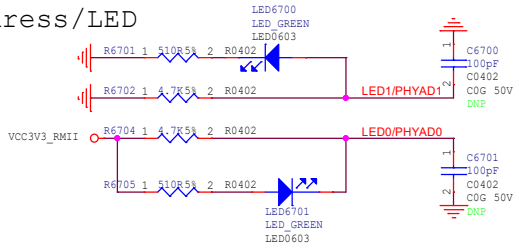


Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd		
Project:	RV1126_RV1109 IPC REF		
File:	61.RK912(option)		
Date:	Friday, December 04, 2020	Rev:	V1.2
Designed by: Yanhong.Li	Reviewed by: <Checker>	Sheet:	38 of 44

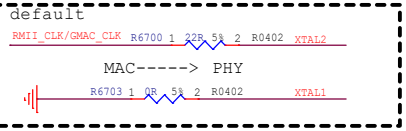
PHY

RMII_TXD0/GMAC_TXD0
RMII_TXD1/GMAC_TXD1
RMII_TXEN/GMAC_TXEN
RMII_RXDV/GMAC_RXDV
RMII_RXER
RMII_RXD0/GMAC_RXD0
RMII_RXD1/GMAC_RXD1
RMII_MDIO/GMAC_MDIO
RMII_MDC/GMAC_MDC
RMII_CLK/GMAC_CLK
EPHY_RSTn
POE12
POE36
POE45
POE78

PHY Address/LED



default



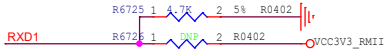
1. No crystal:
R6700,R6703,R6712, R6724 are sodered.
R6708,Y6700,C6702,C6703,R6717 are DNP.

2. With crystal
R6700,R6703,R6712, R6724 are DNP.
R6708,Y6700,C6702,C6703,R6717 are soldered.

MII/RMII Selection

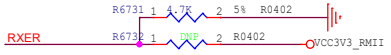
Pull High for RMII mode(default)

WOL/LED0 Selection



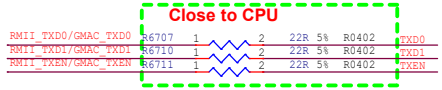
Pull Low for LED0 Mode(default)
Pull High for WOL Mode
WOL:Wake-on-LAN

UTP / Fiber Selection

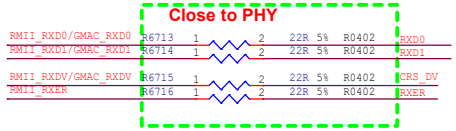


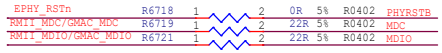
Pull Low for UTP Mode(default)
Pull High for Fiber Mode

Close to CPU

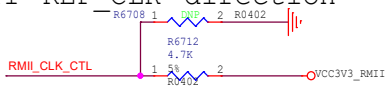


Close to PHY



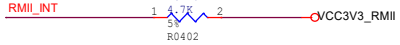


RMII REF_CLK direction

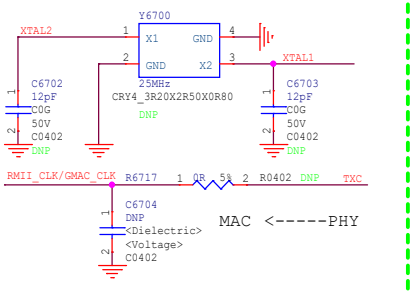


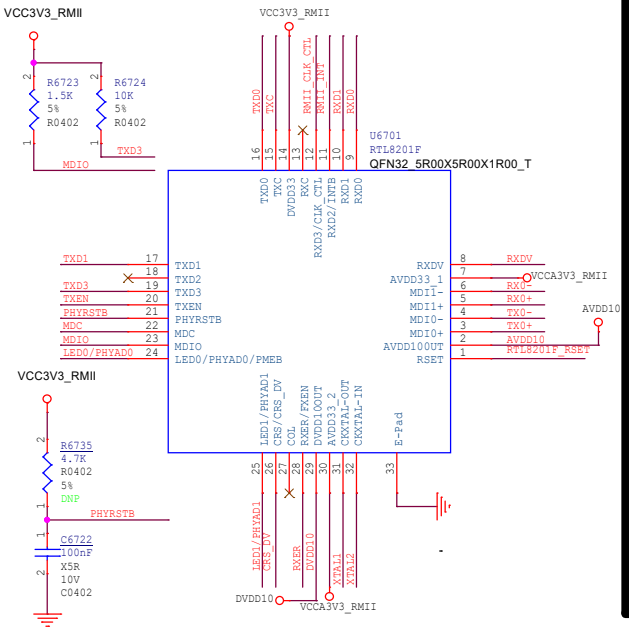
Pull Low for RMII REF_CLK Output mode
Pull High for RMII REF_CLK Input mode

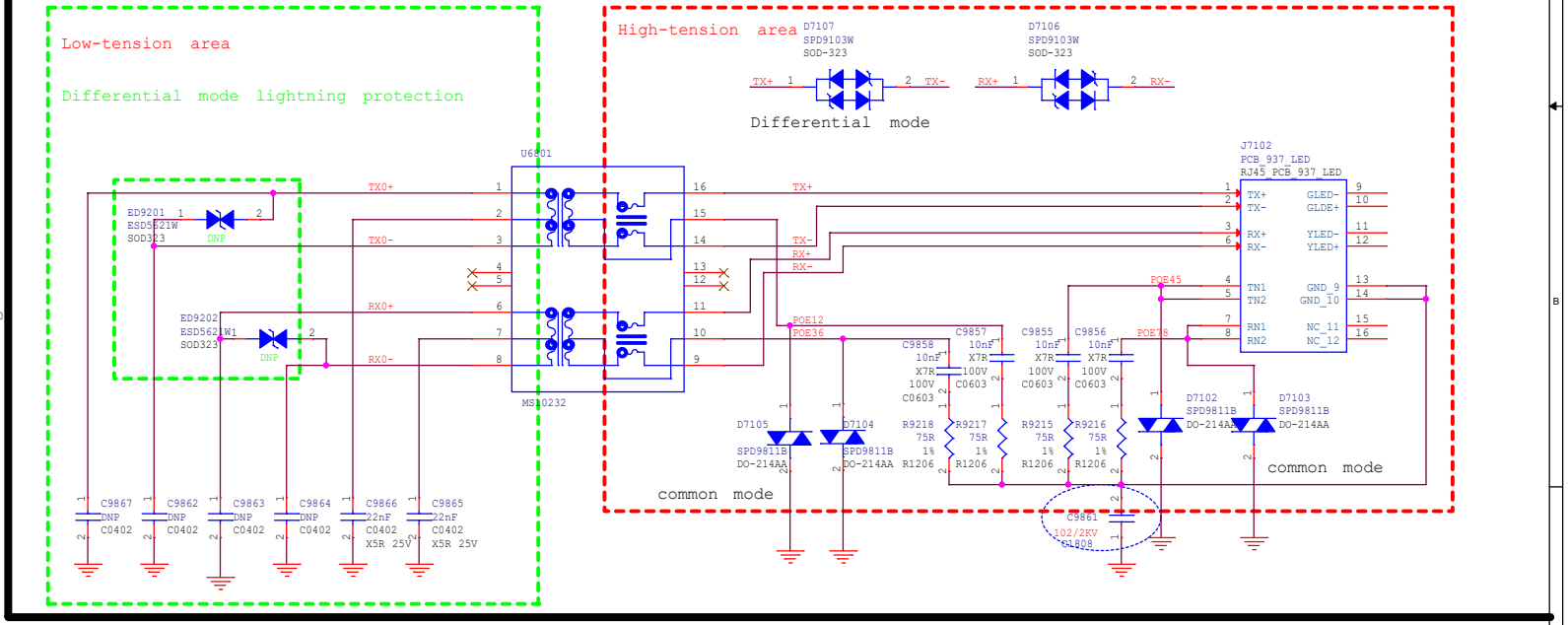
This pin is pulled high by an external 4.7Kohm.
This pin is used for the interrupt function only when in the RMII mode.

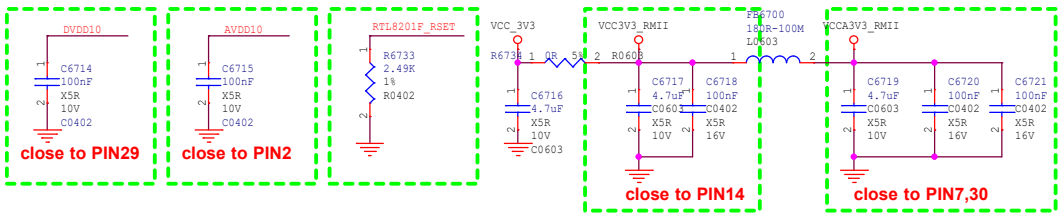


OPTION1









Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	67.Ethernet-EPHY_RMII				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	39 of 44

OPTION:GPHY

10/100/1000M RMII ETHERNET

Close to CPU

Close to PHY

OPTION1

Default

IO pad=1.8V

IO pad=3.3V OPTION1

LINK&ACT

J6800

HR911130C

RJ45_HR911130C

RGMII=3.3V IO,R6824=22R,R6827=DNP
RGMII=1.8V IO,R6824=100R,R6827=120R
If 125M come from RV1126/RV1109,
this part is not used.

MAC <----- PHY

3.3Vpp

CFG_EXT=1:Use the external power source for the IO pad.
CFG_LDO1=1, CFG_LDO0=0: IO pad 1.8V
CFG_LDO1=0,CFG_LDO0=0: IO pad 3.3V

RGMII Power Source	CFG_EXT	CFG_LDO[1:0]
External 3.3V	1'b1	2'b00
External 1.8V (default)	1'b1	2'b10
Internal 1.8V	1'b0	2'b10

VCCIO_PHY Voltage Config

PHY Address Config

PHY Address	PHYAD[2:0]
1 (default)	3'b001

Pull-up for additional 2ns delay to RXC for data latching

Pull-up for additional 2ns delay to TXC for data latching

Pull-up to disable PLL @ ALDPS mode

U6800
RTL8211F-CG
QFN40_5R00X5R00X0R90_T
RTL8211F-CG(SW Mode)
RTL8211FI-CG(SW Mode)Industrial

PHYRSTB is 3.3V IO

close to PIN11,40

close to PIN28

close to PIN30

close to PIN3,8,21,38

close to PIN29

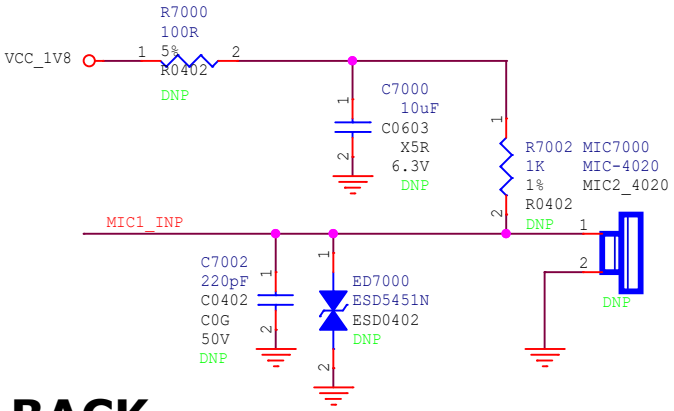
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd		
Project:	RV1126_RV1109 IPC REF		
File:	68.Ethernet-GEPHY_RGMII(option)		
Date:	Friday, December 04, 2020	Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by: <Checker>	Sheet: 40 of 44

Audio1(PMIC RK809-2)

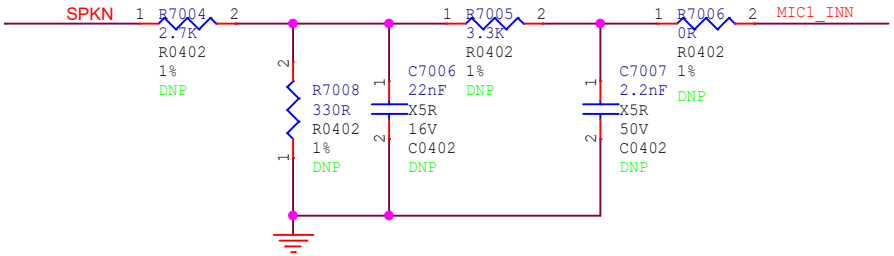
MIC1_INP
MIC1_INN
SPKN_OUT
SPKP_OUT

OPTION1: single end MIC, single loopback

MIC

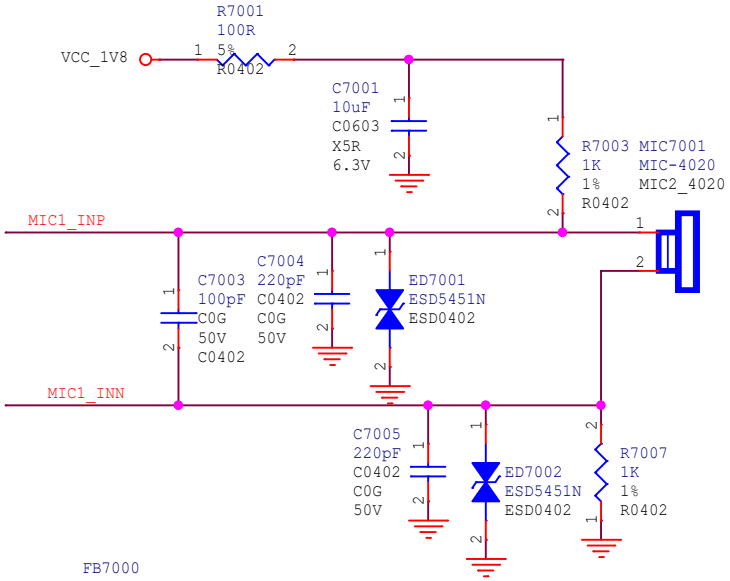


LOOP BACK

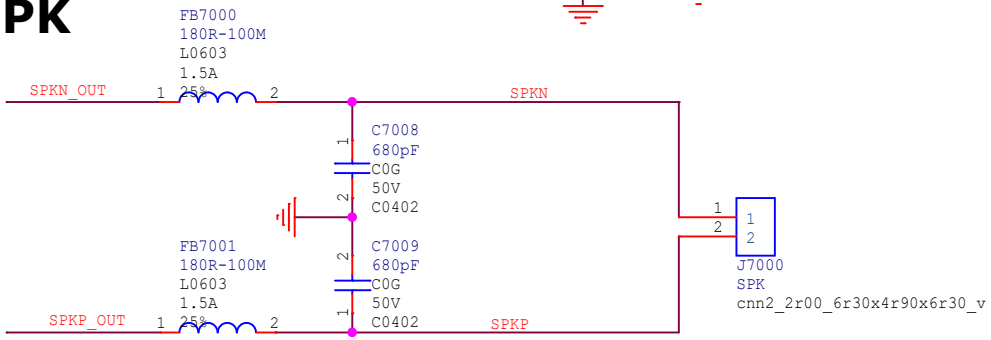


DEFAULT: no loopback, use differential MIC

differential MIC



SPK



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	70.Audio Port1				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	41 of 44

Audio2(PMIC RK809-2+PDM MIC) (option)

MIC1_INN
MIC1_INP
HPL_OUT
HP_SNS
HPR_OUT
SPKN_OUT
SPKP_OUT
PDM_CLK
PDM_SDI3

PDM MIC

2 Digital MEMS MIC or 1

PDM_CLK — R7100 R0402 22R 5% — PDM_CLK_1
PDM_SDI3 — R7103 R0402 22R 5% — PDM_SDI0_1

VCC_MIC
MIC7100
MSM261D4030H1CPM
VDD CLK L/R DATA GND1 GND2 GND3 GND4
C7102 100nF X5R C0402 6.3V
PDM_CLK_1
PDM_SDI0_1
R7106 100K 5% R0402

VCC_MIC
MIC7101
MSM261D4030H1CPM
DNP
VDD CLK L/R DATA GND1 GND2 GND3 GND4
C7103 100nF X5R C0402 6.3V

VCC_1V8 — FB7102 L0603 — 180R-100M 1.5A 25% — VCC_MIC

NOTE:
The SDI line should have a 100kohm PD resistor to discharge the line during the time that all microphones on the bus have tristated their outputs.

SPK OUT

SPKN_OUT — FB7100 180R-100M L0603 1.5A 25% — SPKN1
C7100 680pF C0G 50V C0402
FB7101 180R-100M L0603 1.5A 25%
C7101 680pF C0G 50V C0402
SPKP_OUT — SPKP1
J7100 SPK cnn2_2r00_6r30x4r90x6r30_v

OPTION LINE OUT

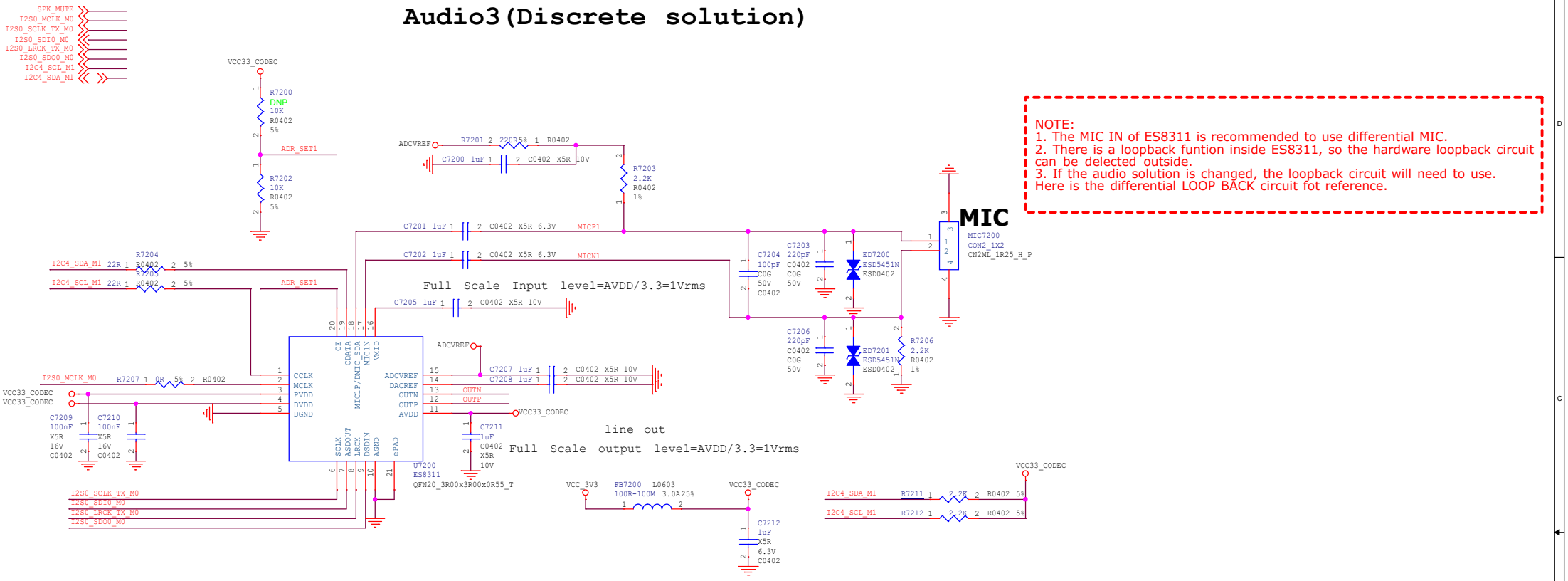
HPL_OUT — R7101 22R 5% R0402
HP_SNS — R7102 22R 5% R0402
HPR_OUT — R7104 22R 5% R0402
J7101 CON3_1X3
D7100 ESD5341N ESD0402
D7101 ESD5341N ESD0402
R7105 0R 5% R0402 DNP

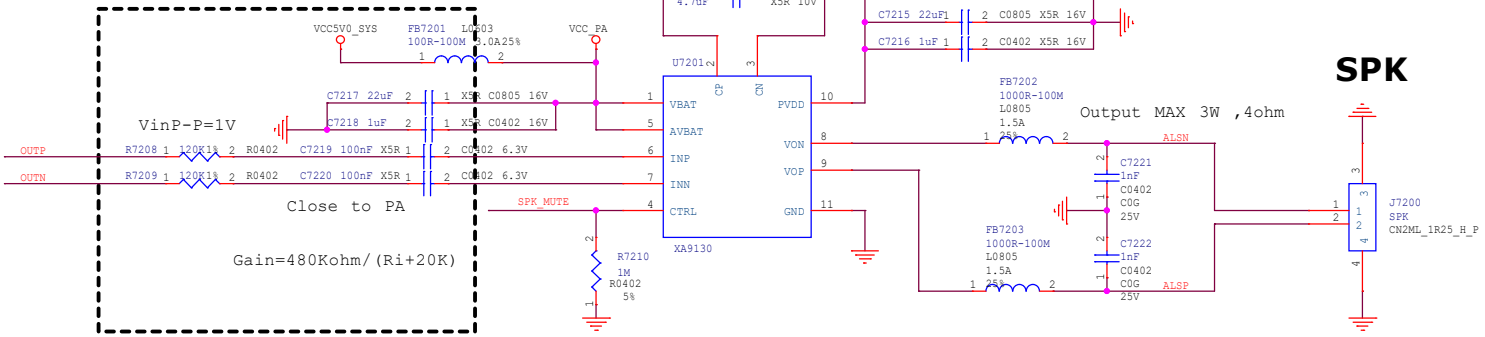
Differential LOOP BACK

SPKN1 — R7107 5.1K R0402 1% — R7108 1K R0402 1% — MIC1_INN
R7109 220R R0402 1%
C7104 22nF X5R 25V C0402
C7105 10nF X5R 25V C0402
R7110 220R R0402 1%
C7106 22nF X5R 25V C0402
C7107 10nF X5R 25V C0402
SPKP1 — R7111 5.1K R0402 1% — R7112 1K R0402 1% — MIC1_INP

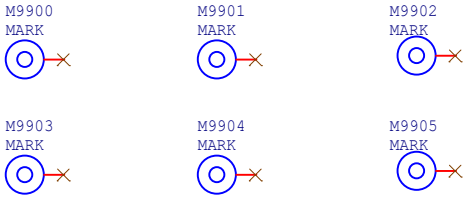
Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	71.Audio Port2(option)				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	42 of 44

Audio3(Discrete solution)





Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	72_Audio Port3(ES8311)				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	43 of 44



Rockchip 瑞芯微电子	Rockchip Electronics Co., Ltd				
Project:	RV1126_RV1109 IPC REF				
File:	99.MARK				
Date:	Friday, December 04, 2020			Rev:	V1.2
Designed by:	Yanhong.Li	Reviewed by:	<Checker>	Sheet:	44 of 44